

# Type 1DX Wi-Fi® + Bluetooth® Module

Infineon CYW4343W Chipset for 802.11b/g/n + Bluetooth 5.1 Datasheet - Rev. W

- Design Name: Type 1DX
- Module P/N: LBEE5KL1DX-883



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## About This Document

Type 1DX is a small and high performance module based on Infineon CYW4343W combo chipset which supports Wi-Fi 802.11b/g/n + Bluetooth 5.1 BR/EDR/LE. This datasheet describes Type 1DX module in detail.



Please be aware that an important notice concerning availability, standard warranty and use in critical applications of Murata products and disclaimers thereto appears at the end of this specification sheet.









## Audience & Purpose

Intended audience includes any customer looking to integrate this module into their product; specifically RF, hardware, software, and systems engineers.

## Document Conventions

**Table 1** describes the document conventions.


**Table 1: Document Conventions**

Conventions	Description
	<b>Warning Note</b> Indicates very important note. Users are strongly recommended to review.
	<b>Info Note</b> Intended for informational purposes. Users should review.
	<b>Menu Reference</b> Indicates menu navigation instructions. <b>Example:</b> Insert → Tables → Quick Tables → Save Selection to Gallery 
	<b>External Hyperlink</b> This symbol indicates a hyperlink to an external document or website. <b>Example:</b> <a href="#">Murata</a>  Click on the text to open the external link.
	<b>Internal Hyperlink</b> This symbol indicates a hyperlink within the document. <b>Example:</b> <a href="#">Scope</a>  Click on the text to open the link.
<code>Console input/output or code snippet</code>	<b>Console I/O or Code Snippet</b> This text <b>Style</b> denotes console input/output or a code snippet.
<code># Console I/O comment // Code snippet comment</code>	<b>Console I/O or Code Snippet Comment</b> This text <b>Style</b> denotes a console input/output or code snippet comment. <ul style="list-style-type: none"> <li>• Console I/O comment (preceded by "#") is for informational purposes only and does not denote actual console input/output.</li> <li>• Code Snippet comment (preceded by "//") may exist in the original code.</li> </ul>

## 1 Scope

This specification characterizes the IEEE 802.11b/g/n + Bluetooth Ver. 5.1 (BR/EDR/BLE) combo module.

## 2 Key Features

- ◆ Infineon CYW4343W inside
- ◆ Supports IEEE 802.11b/g/n specification: 2.4 GHz.
- ◆ Up to 65 Mbps PHY data rates
- ◆ Supports Bluetooth specification version 5.1
- ◆ For supported Bluetooth functions, refer to [Bluetooth SIG site](#) 
- ◆ WLAN Interface: SDIO 3.0
- ◆ Bluetooth interface: HCI UART and PCM
- ◆ Temperature range: -30 °C to 70 °C
- ◆ Dimensions: 6.95 x 5.15 x 1.1 mm
- ◆ MSL: 3
- ◆ Surface mount type
- ◆ RoHS compliant
- ◆ Reference Clock: Embedded

## 3 Ordering Information

**Table 2** describes the ordering information.

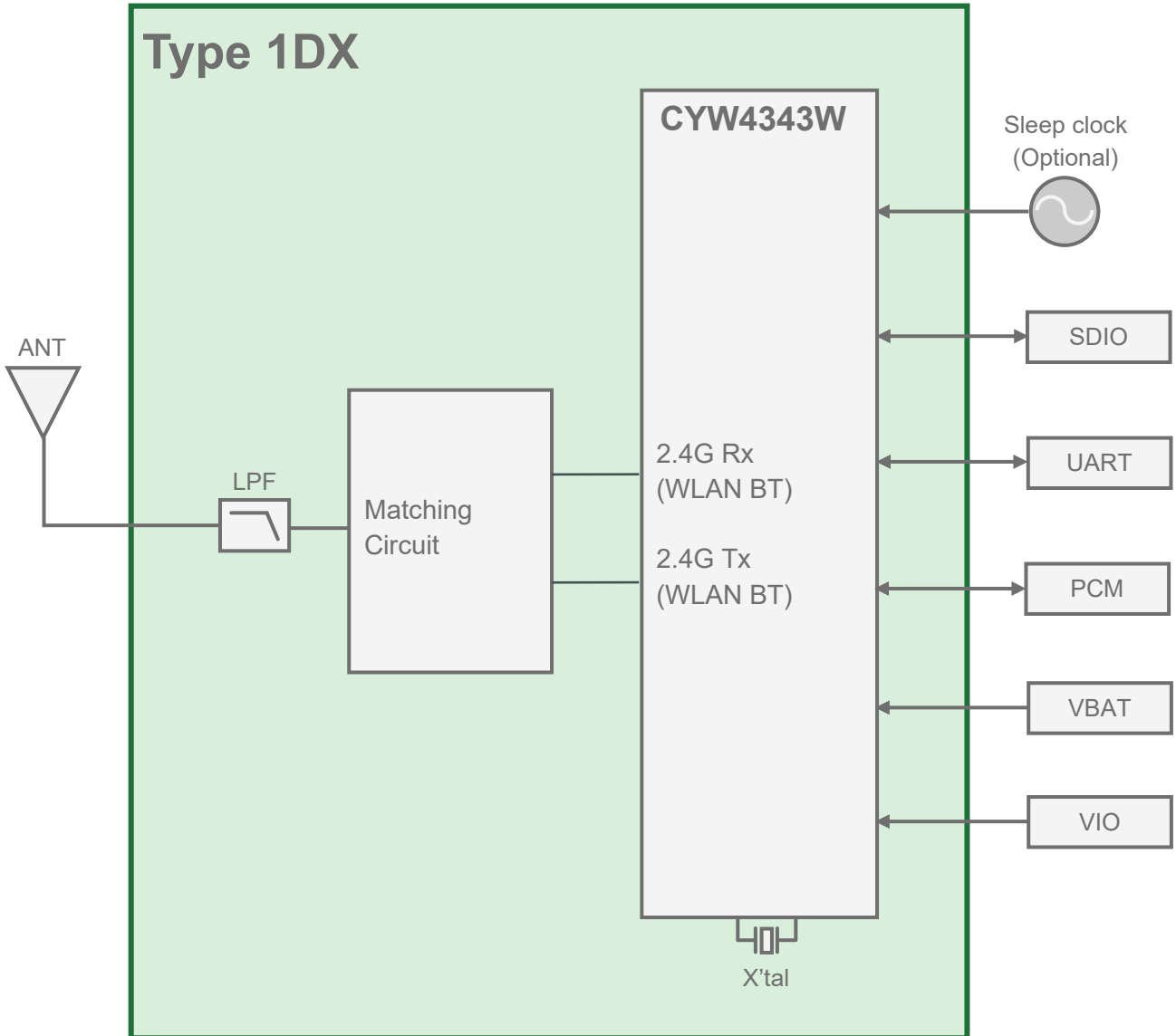
**Table 2: Ordering Information**

Ordering Part Number	Description
LBEE5KL1DX-883	Module order
LBEE5KL1DX-TEMP	Sample module order (If module samples are not available through distribution, contact Murata referencing this part number)
EAR00318	Embedded Artists Type 1DX M.2 EVB (default EVB available through distribution)
LBEE5KL1DX-TEMP-D	Murata Type 1DX M.2 EVB (contact Murata as this is special order item)

## 4 Block Diagram

Figure 1 shows the Type 1DX block diagram.

Figure 1: Block Diagram






## 5 Certification Information

This section has information about radio and Bluetooth certification.


### 5.1 Radio Certification

**Table 3** shows the radio certification information.

**Table 3: Certification Information**

Country	ID	Country Code
USA (FCC)	VPYLB1DX	US
Canada (IC)	772C-LB1DX	CA
Europe	EN300328 v2.1.1 conducted test report is prepared.	DE
Japan	Japanese type certification is prepared.  01-P00840	JP



Please follow installation manual in [Section 16](#) .

### 5.2 Bluetooth Qualification

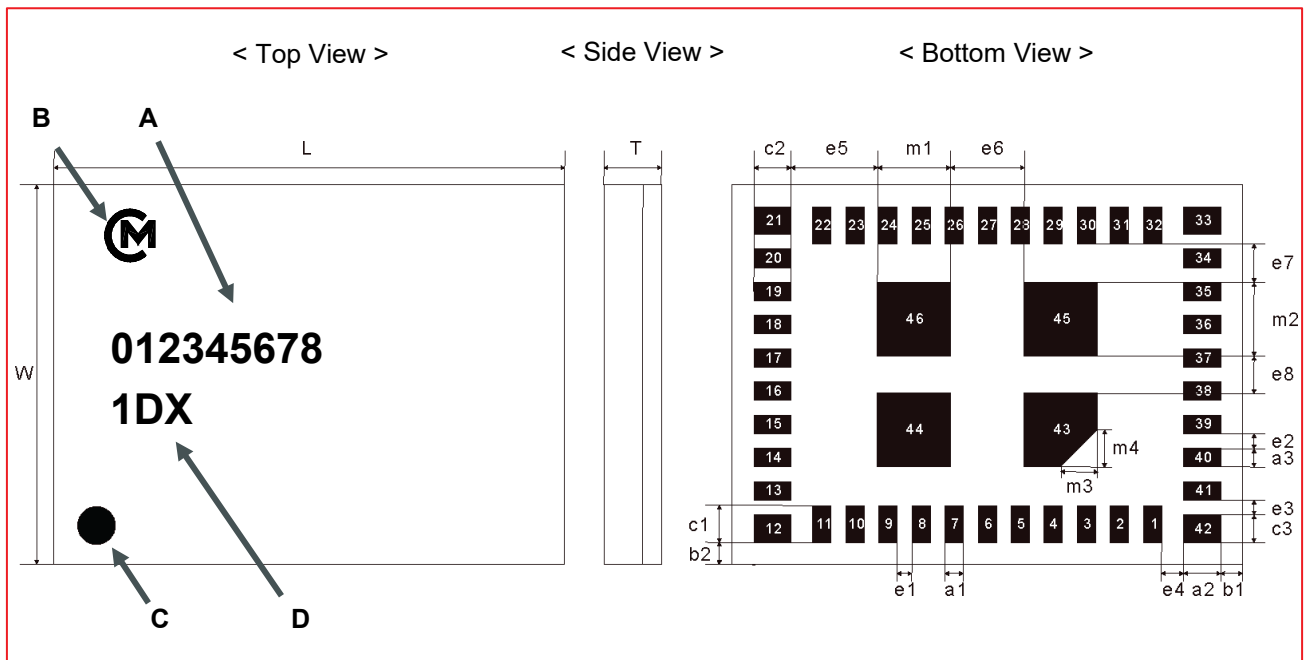
- QDID: 140301
- For supported Bluetooth functions, refer to [Bluetooth SIG site](#) 

## 6 Dimensions, Markings and Terminal Configurations

This section has information on dimensions, markings, and terminal configurations for Type 1DX.

**Figure 2** shows the dimensions, marking, and terminal configurations. **Table 4** and **Table 5** describes the Type 1DX markings and dimensions.

**Figure 2: Dimension, Markings and Terminal Configuration**



**Table 4: Markings**

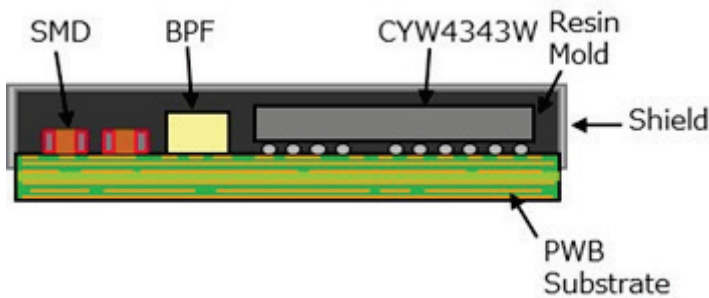
Marking	Meaning
A	Inspection Number
B	Murata Logo
C	Pin 1 Marking
D	Module Type

**Table 5: Dimensions**

Mark	Dimensions (mm)	Mark	Dimensions (mm)	Mark	Dimensions (mm)
L	6.95 +/- 0.2	W	5.15 +/- 0.2	T	1.1 maximum
a1	0.25 +/- 0.10	a2	0.5 +/- 0.1	a3	0.25 +/- 0.10
b1	0.30 +/- 0.2	b2	0.30 +/- 0.2	c1	0.50 +/- 0.1
c2	0.50 +/- 0.1	c3	0.375 +/- 0.100	e1	0.2 +/- 0.1
e2	0.2 +/- 0.1	e3	0.2 +/- 0.1	e4	0.3 +/- 0.1
e5	1.175 +/- 0.100	e6	1.0 +/- 0.1	e7	0.525 +/- 0.100
e8	0.50 +/- 0.10	m1	1.0 +/- 0.1	m2	1.0 +/- 0.1
m3	0.5 +/- 0.1	m4	0.5 +/- 0.1		

**Figure 3** shows the structure of Type 1DX module.

**Figure 3: Structure**



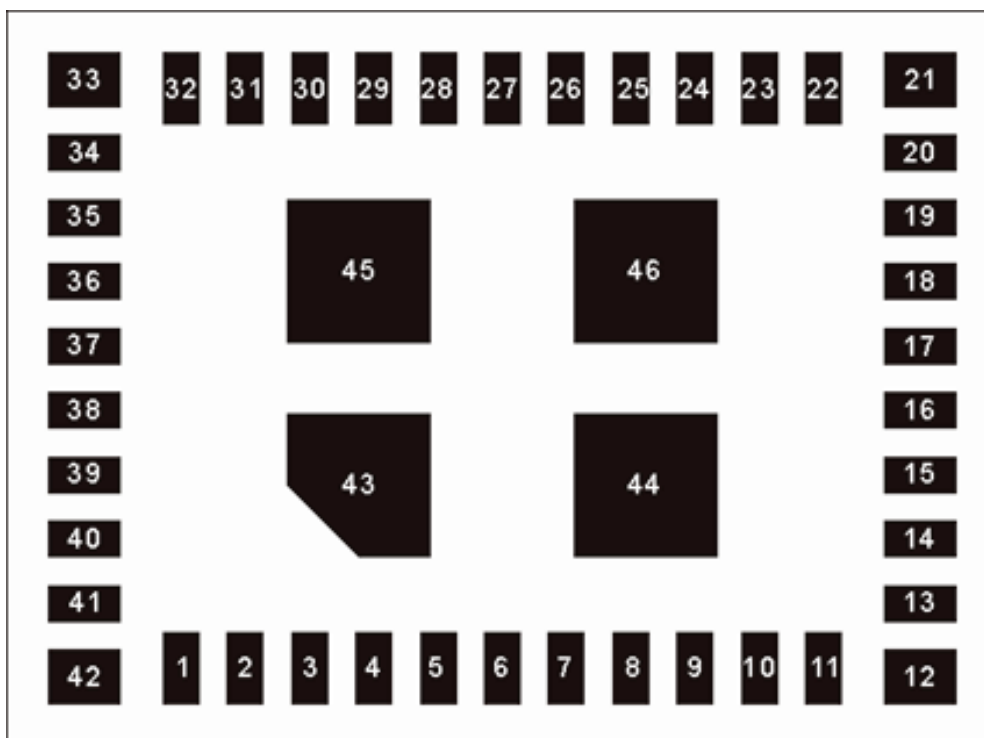
## 7 Module Pin Descriptions

This section has the pin descriptions of Type 1DX and pin assignments layout descriptions.

### 7.1 Module Pin Layout

The pin assignment (top view) layout is shown in **Figure 4**.

**Figure 4: Pin Assignments Top View**



**Table 6** illustrates the terminal configurations.

**Table 6: Terminal Configurations**

No.	Terminal Name	No.	Terminal Name	No.	Terminal Name
1	GND	15	WL_GPIO_4	29	GND
2	BT_UART_RXD	16	BT_I2S_dO	30	VBAT
3	BT_UART_TXD	17	WL_GPIO_2	31	VIN_LDO
4	BT_UART_CTS_N	18	WL_GPIO_1	32	GND (SR_PVSS)
5	BT_UART_RTS_N	19	GND	33	GND (SR_PVSS)
6	BT_GPIO_3	20	SDIO_CLK	34	SR_VLX
7	BT_GPIO_4	21	GND	35	GND
8	BT_PCM_SYNC	22	SDIO_CMD	36	VIO
9	BT_PCM_IN	23	SDIO_DATA_2	37	LPO_IN (32 kHz)
10	BT_PCM_OUT	24	SDIO_DATA_0	38	BT_HOST_WAKE
11	BT_PCM_CLK	25	SDIO_DATA_3	39	BT_DEV_WAKE
12	GND	26	SDIO_DATA_1	40	GND
13	BT_GPIO_5	27	WL_GPIO_0_HOST_WAKE	41	ANT
14	BT_REG_ON	28	WL_REG_ON	42~46	GND

## 7.2 Pin Descriptions

**Table 7** describes Type 1DX pins.

**Table 7: Pin Descriptions**

No.	Pin name	Type	Connection to IC Pin Name	Description
1	GND			
2	BT_UART_RXD	I	BT_UART_RXD	UART serial input. Serial data input for the HCI UART interface.
3	BT_UART_TXD	O	BT_UART_TXD	UART serial output. Serial data output for the HCI UART interface.
4	BT_UART_CTS_N	I	BT_UART_CTS_N	UART clear-to-send. Active-low clear-to-send signal for the HCI UART interface.
5	BT_UART_RTS_N	O	BT_UART_RTS_N	UART request-to-send. Active-low request-to-send signal for the HCI UART interface.
6	BT_GPIO_3		BT_GPIO_3	
7	BT_GPIO_4		BT_GPIO_4	
8	BT_PCM_SYNC	I/O	BT_PCM_SYNC	PCM sync; can be master (output) or slave (input)
9	BT_PCM_IN	I	BT_PCM_IN	PCM data input sensing
10	BT_PCM_OUT	O	BT_PCM_OUT	PCM data output
11	BT_PCM_CLK	I/O	BT_PCM_CLK	PCM clock; can be master (output) or slave (input)
12	GND			

No.	Pin name	Type	Connection to IC Pin Name	Description
13	BT_GPIO_5		BT_GPIO_5	
14	BT_REG_ON	I	BT_REG_ON	Used by PMU to power up or power down the internal regulators used by the Bluetooth section. Also, when de-asserted, this pin holds the Bluetooth section in reset. This pin has an internal 200kΩ pull-down resistor that is enabled by default. It can be disabled through programming.
15	WL_GPIO_4		GPIO_4	
16	BT_I2S_dO			
17	WL_GPIO_2		GPIO_2	
18	WL_GPIO_1		GPIO_1	
19	GND			
20	SDIO_CLK	I		SDIO clock input.
21	GND			
22	SDIO_CMD	I/O	SDIO_CMD	SDIO command line
23	SDIO_DATA_2	I/O	SDIO_DATA_2	SDIO data line 2
24	SDIO_DATA_0	I/O	SDIO_DATA_0	SDIO data line 0
25	SDIO_DATA_3	I/O	SDIO_DATA_3	SDIO data line 3
26	SDIO_DATA_1	I/O	SDIO_DATA_1	SDIO data line 1
27	WL_GPIO_0_HOST_WAKE		GPIO_0	
28	WL_REG_ON	I	WL_REG_ON	Used by PMU to power up or power down the internal regulators used by the WLAN section. Also, when de-asserted, this pin holds the WLAN section in reset. This pin has an internal 200kΩ pull-down resistor that is enabled by default. It can be disabled through programming.
29	GND			
30	VBAT		LDO_VDDBAT5V, SR_VDDBAT5V	
31	VIN_LDO		LDO_VDD1P5, WLRV_VDD_1P35	
32	GND (SR_PVSS)			
33	GND (SR_PVSS)			
34	SR_VLX		SR_VLX	CBUCK switching regulator output.
35	GND			
36	VIO		SCC_VDDIO, SYS_VDDIO	
37	LPO_IN (32 kHz)	I	LPO_IN	External sleep clock input (32.768 kHz).
38	BT_HOST_WAKE	I/O	BT_HOST_WAKE	HOST_WAKE or general-purpose I/O signal
39	BT_DEV_WAKE	I/O	BT_DEV_WAKE	DEV_WAKE or general-purpose I/O signal
40	GND			
41	ANT			
42 ~	GND			

No.	Pin name	Type	Connection to IC Pin Name	Description
46				

### 7.3 SDIO Pin Descriptions

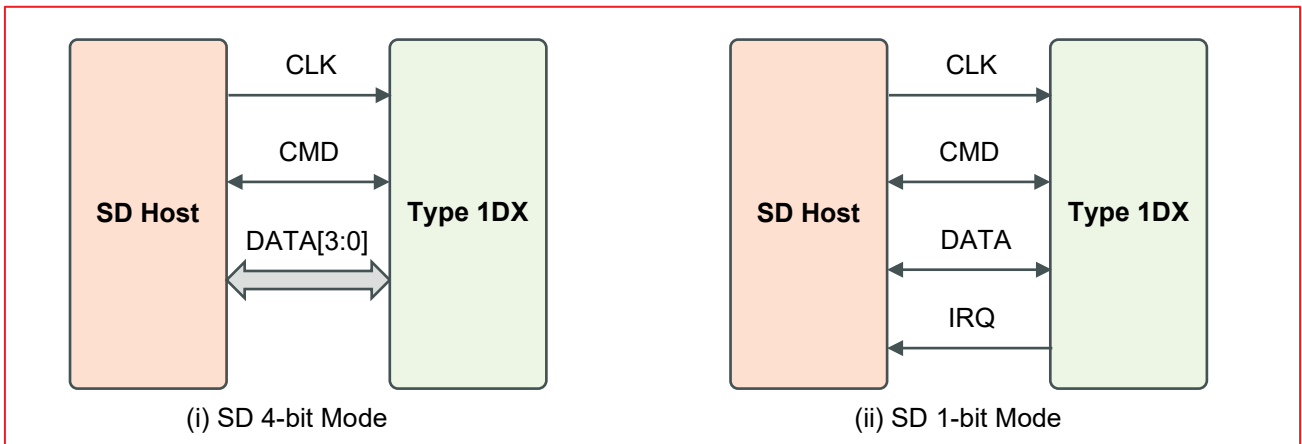
This section describes the SDIO pins and UART connections. **Table 8** shows the SDIO pin descriptions.

**Table 8: SDIO Pin Descriptions**

No.	Pin Name	(i) SD 4-bit Mode		(ii) SD 1-bit Mode	
20	SDIO_CLK	CLK	Clock	CLK	Clock
24	SDIO_D0	DATA0	Data line 0	DATA	Data line
26	SDIO_D1	DATA1	Data line 1 /Interrupt	IRQ	Interrupt
23	SDIO_D2	DATA2	Data line 2	NC	Not used
25	SDIO_D3	DATA3	Data line 3	NC	Not used
22	SDIO_CMD	CMD	Command line	CMD	Command line

**Figure 5** shows the SDIO pins.

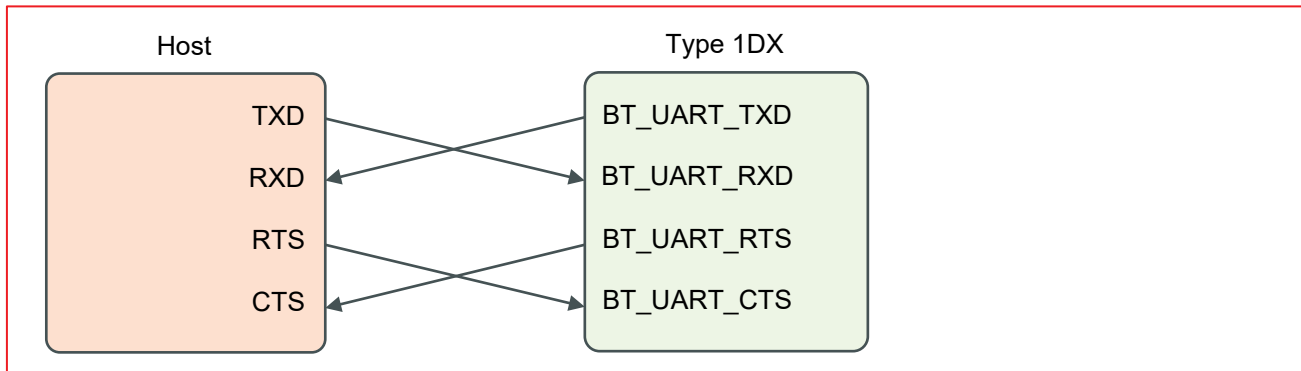
**Figure 5: SDIO Pins**



10 to 100 kΩ pull-ups are required on the four DATA lines and the CMD line. This requirement must be met during all operating states by using external pull-up resistors or properly programming internal SDIO host pull-ups.

The UART connection is shown in **Figure 6**.

**Figure 6: UART Connection**



## 8 Absolute Maximum Ratings

The minimum and maximum ratings are shown in **Table 9**.

**Table 9: Absolute Maximum Ratings**

Parameter		Minimum	Maximum	Unit
Storage Temperature		-40	+85	°C
Supply Voltage	VBAT	-0.5	5.0	V
	VDDIO	-0.5	3.9	V



Stresses in excess of the absolute ratings may cause permanent damage. Functional operation is not implied under these conditions. Exposure to absolute ratings for extended periods of time may adversely affect reliability. No damage assuming only one parameter is set at limit at a time with all other parameters are set within operating condition.

## 9 Operating Conditions

The operating conditions are shown in **Table 10**.

**Table 10: Operating Conditions**

Parameter		Minimum	Typical	Maximum	Unit
Operating Temperature Range		-30	+25	+70	°C
Specification Temperature Range		-10	+25	+55	°C
Operating Voltage	VBAT	3.0	3.6	4.8	V
	VDDIO	1.71	1.8 or 3.3	3.63	V
Specification Voltage	VBAT	3.2	3.6	4.2	V
	VDDIO	1.71	1.8 or 3.3	3.63	V



All RF characteristics in this datasheet are defined by specification temperature range and specification voltage.

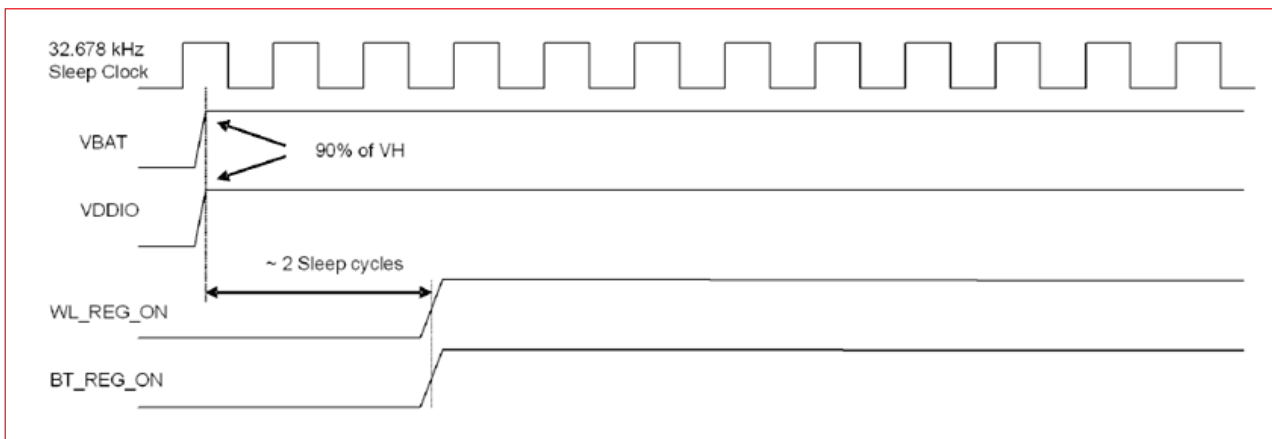
## 10 Power-On Sequences

This section describes the power-on sequences along with their parameters.

- VBAT should not rise 10%-90% faster than 40 microseconds.
- VBAT should be up before or at the same time as VIO. VIO should not be present fast or be held high before VBAT is high.

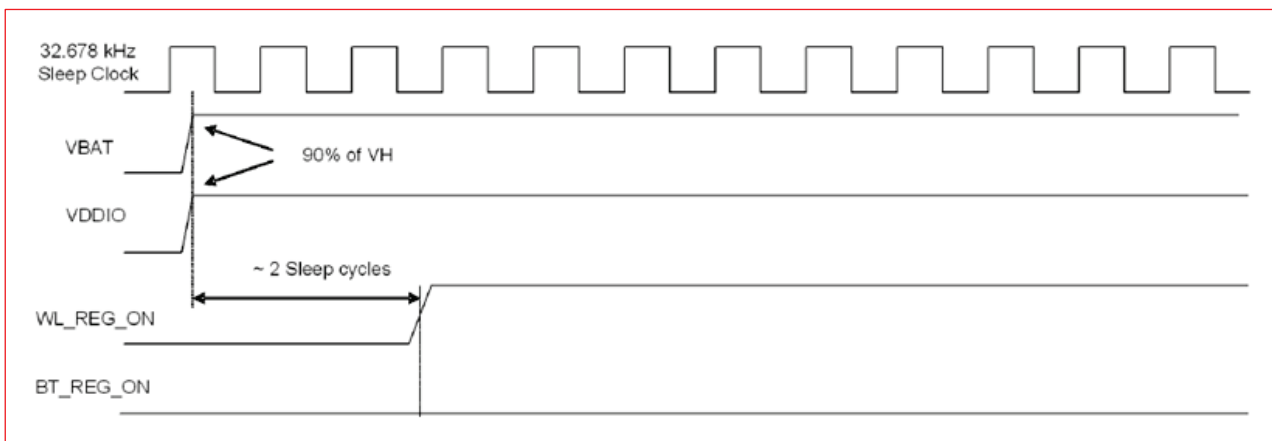
**Figure 7** shows the power-on sequence graphs for WLAN ON and BT ON.

**Figure 7: Power-On Sequence Graph - WLAN ON and BT ON**



**Figure 8** shows power-on sequence graph for WLAN ON and BT OFF.

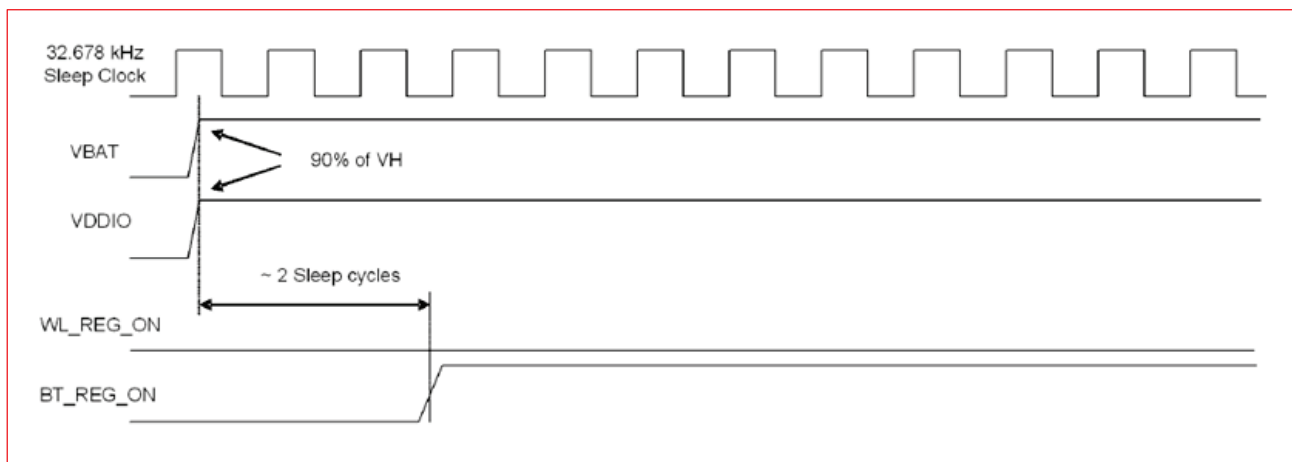
**Figure 8: Power-On Sequence Graph - WLAN ON and BT OFF**





**Figure 9** power-on sequence graph for WLAN OFF and BT ON.

**Figure 9: Power-On Sequence Graph - WLAN OFF and BT ON**



**Figure 10** shows power-on sequence graph for WLAN OFF and BT OFF.

**Figure 10: Power-On Sequence Graph - WLAN OFF and BT OFF**

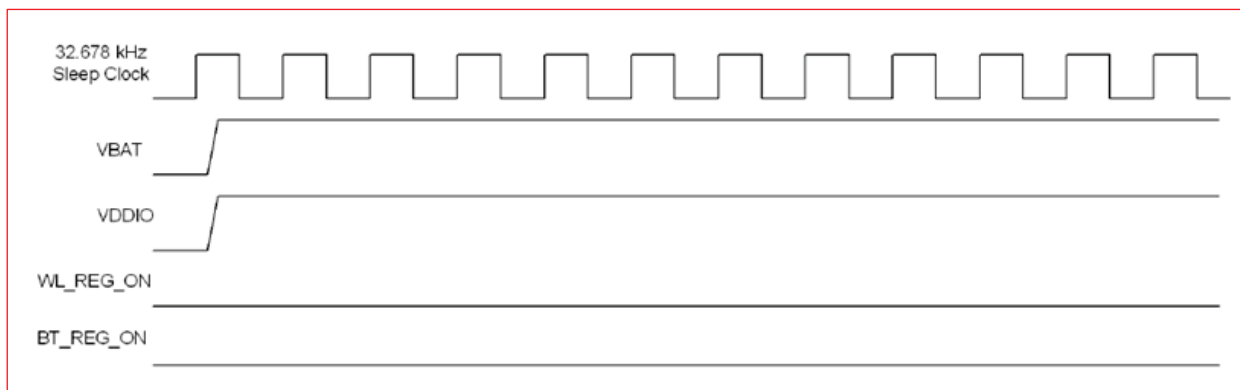
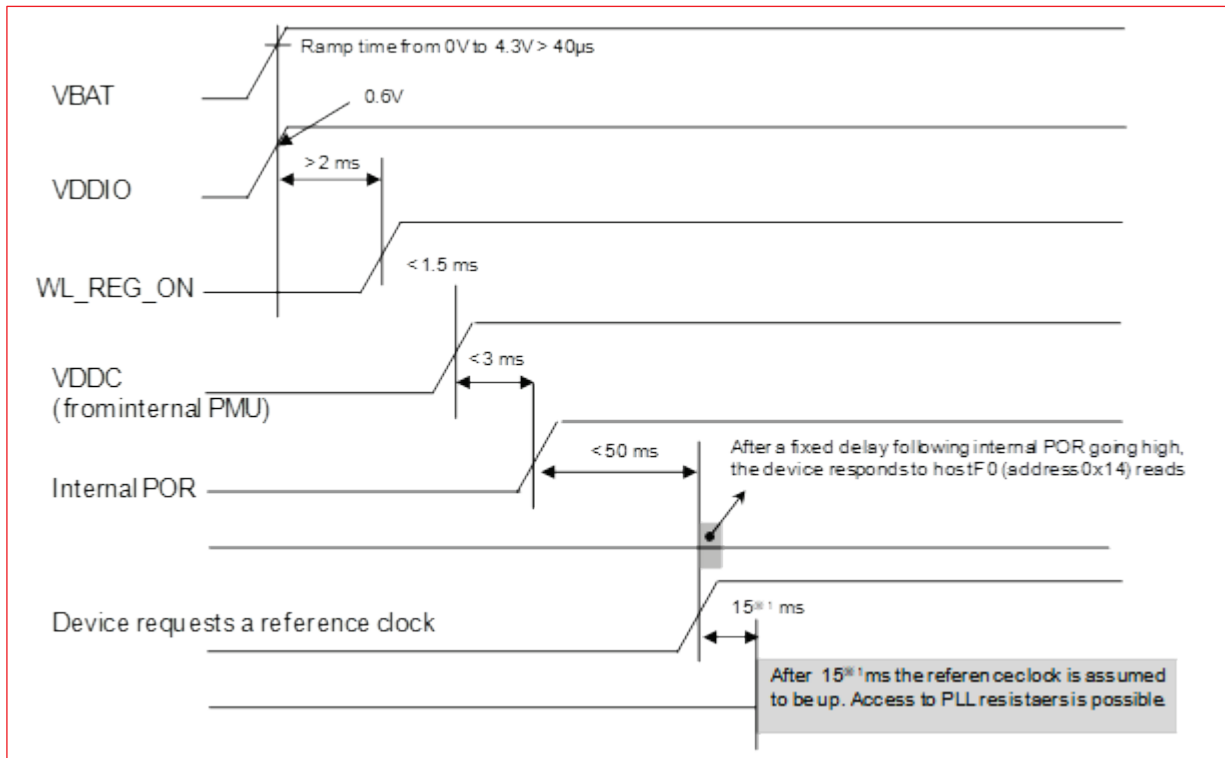


Figure 11 shows WLAN boot up sequence.

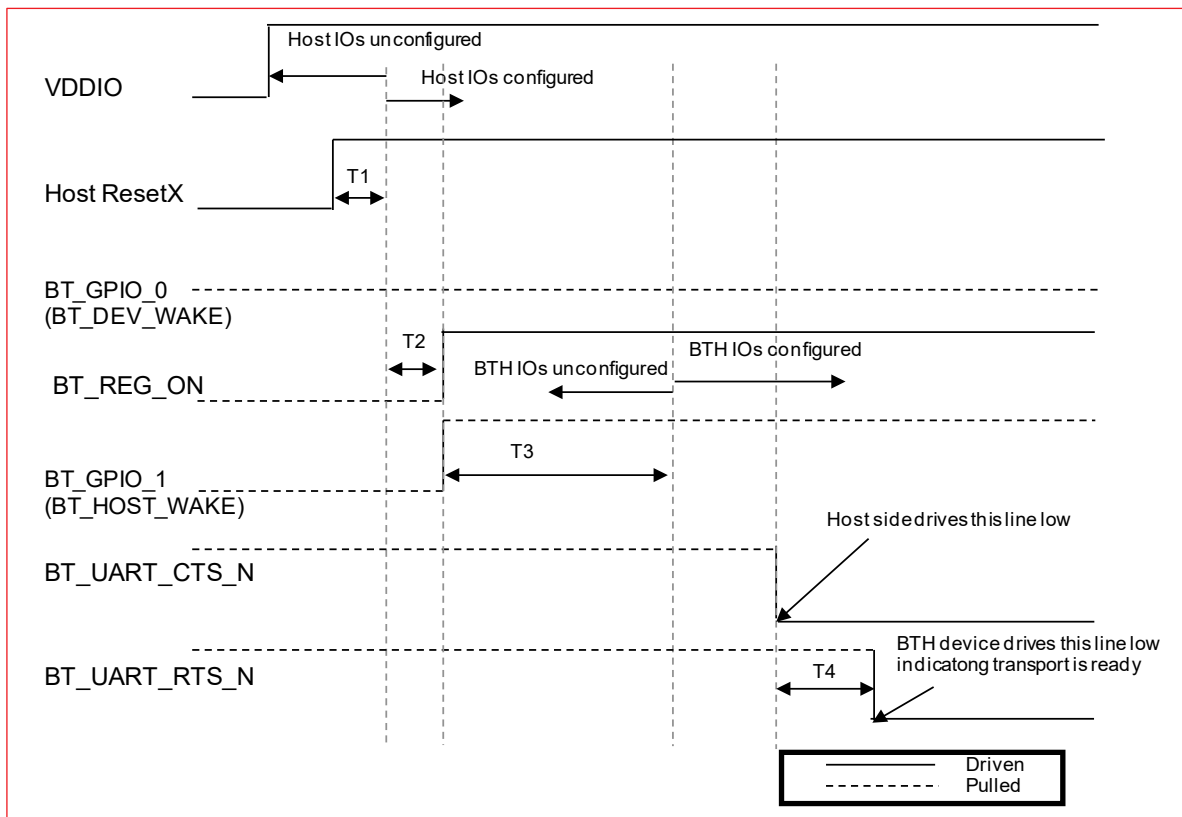
Figure 11: WLAN Boot Up Sequence



※1 This wait time is programmable in sleep-clock increments from 1 to 255 (30 µs to 15 ms).

Figure 12 shows the startup signaling sequence.

Figure 12: Startup Signaling Sequence



In this sequence:

- **T1** is the time for host to settle its I/Os after a reset.
- **T2** is the time for host to drive BT\_REG\_ON high after the Host I/Os are configured.
- **T3** is the time for BTH(Bluetooth) device to settle its I/Os after a reset and reference clock settling time has elapsed.
- **T4** is the time for BTH device to drive BT\_UART\_RTS\_N low after the host drives BT\_UART\_CTS\_N low. This assumes the BTH device has already completed initialization.



Timing diagram assumes that VBAT is present.

## 11 Digital I/O Requirements

This section describes the SDIO interface and other digital pins and related parameters. **Table 11** shows the SDIO interface I/O pins.

**Table 11: Digital I/O Requirement Pins**

SDIO Interface I/O Pins	Symbol	Minimum	Maximum	Unit
Input low voltage (VDDIO = 3.3V)	V <sub>IL</sub>		0.25*VDDIO	V
Input high voltage (VDDIO = 3.3V)	V <sub>IH</sub>	0.625*VDDIO		V
Input low voltage (VDDIO = 1.8V)	V <sub>IL</sub>		0.58	V
Input high voltage (VDDIO = 1.8V)	V <sub>IH</sub>	1.27		V
Output low voltage (VDDIO = 3.3V)	V <sub>OL</sub>		0.125*VDDIO	V
Output high voltage (VDDIO = 3.3V)	V <sub>OH</sub>	0.75*VDDIO		V
Output low voltage (VDDIO = 1.8V)	V <sub>OL</sub>		0.45	V
Output high voltage (VDDIO = 1.8V)	V <sub>OH</sub>	1.40		V

**Table 12** shows the other digital I/O pins.

**Table 12: Other Digital I/O Pins**

Other Digital I/O Pins	Symbol	Minimum	Maximum	Unit
Input low voltage (VDDIO = 3.3V)	V <sub>IL</sub>		0.8	V
Input high voltage (VDDIO = 3.3V)	V <sub>IH</sub>	2.0		V
Input low voltage (VDDIO = 1.8V)	V <sub>IL</sub>		0.35*VDDIO	V
Input high voltage (VDDIO = 1.8V)	V <sub>IH</sub>	0.65*VDDIO		V
Output low voltage (VDDIO = 3.3V)	V <sub>OL</sub>		0.40	V
Output high voltage (VDDIO = 3.3V)	V <sub>OH</sub>	VDDIO-0.4		V
Output low voltage (VDDIO = 1.8V)	V <sub>OL</sub>		0.45	V
Output high voltage (VDDIO = 1.8V)	V <sub>OH</sub>	VDDIO-0.45		V

## 12 External Sleep Clock Requirement

**Table 13** shows the external LPO specification of the module.

**Table 13: External LPO Specification**

Parameter	Condition/Notes	Specification			
		Minimum	Typical	Maximum	Units
Frequency			32.768		KHz
Frequency accuracy		-200		+200	ppm
Duty Cycle		30		70	%
Input amplitude		200		3300	mV, p-p
Signal type	Square wave or sine wave				
Input impedance <sup>1</sup>	Resistive	100			kΩ
	Capacitive			5	pF
Clock jitter				10,000	ppm

<sup>1</sup> When power is applied or switched off.

## 13 Interface Timing

This section describes the interface timing for SDIO, Bluetooth, and PCM, their speed modes, related parameters, and graphs.

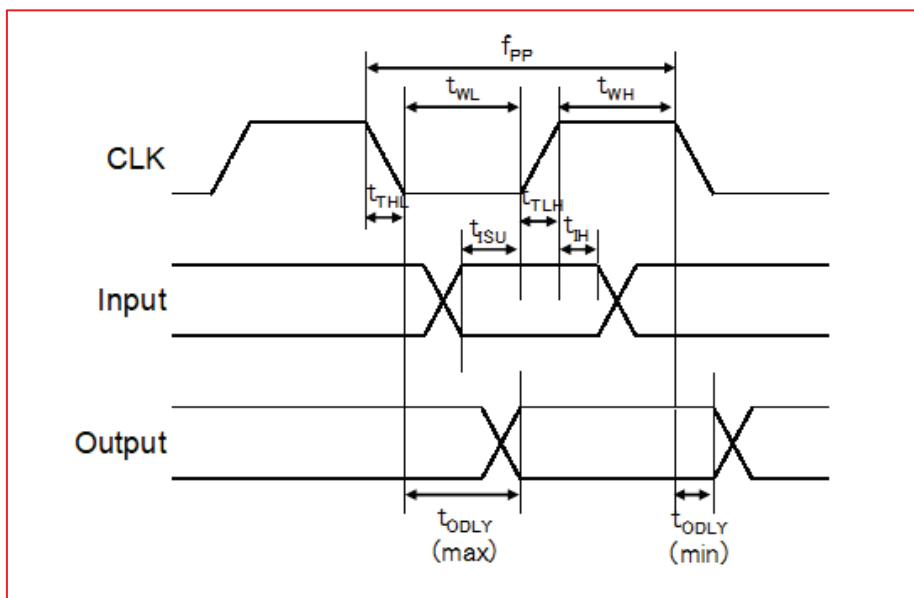
### 13.1 SDIO Timing

This section describes the SDIO signal timing at default and high-speed modes.

#### 13.1.1 Default Mode

The default-speed mode SDIO timing and its parameters are shown in **Figure 13** and **Table 14**.

**Figure 13: SDIO Timing Diagram - Default Mode**



**Table 14: SDIO Timing Parameters - Default Mode**

Parameter	Symbol	Minimum	Typical	Maximum	Unit
<b>Clock CLK (All values are referred to minimum VIH and maximum VIL)</b>					
Frequency-Data Transfer Mode	$f_{PP}$	0		25	MHz
Frequency-Identification Mode	$f_{OD}$	0		400	kHz
Clock Low Time	$t_{WL}$	10			ns
Clock High Time	$t_{WH}$	10			ns
Clock Rise Time	$t_{TLH}$			10	ns
Clock Fall Time	$t_{THL}$			10	ns
<b>Inputs: CMD, DAT (referenced to CLK)</b>					
Input Setup Time	$t_{ISU}$	5			ns
Input Hold Time	$t_{IH}$	5			ns
<b>Outputs: CMD, DAT (referenced to CLK)</b>					

Parameter	Symbol	Minimum	Typical	Maximum	Unit
Output Delay Time-Data Transfer Mode	$t_{ODLY}$	0		14	ns
Output Delay Time-Identification Mode	$t_{ODLY}$	0		50	ns

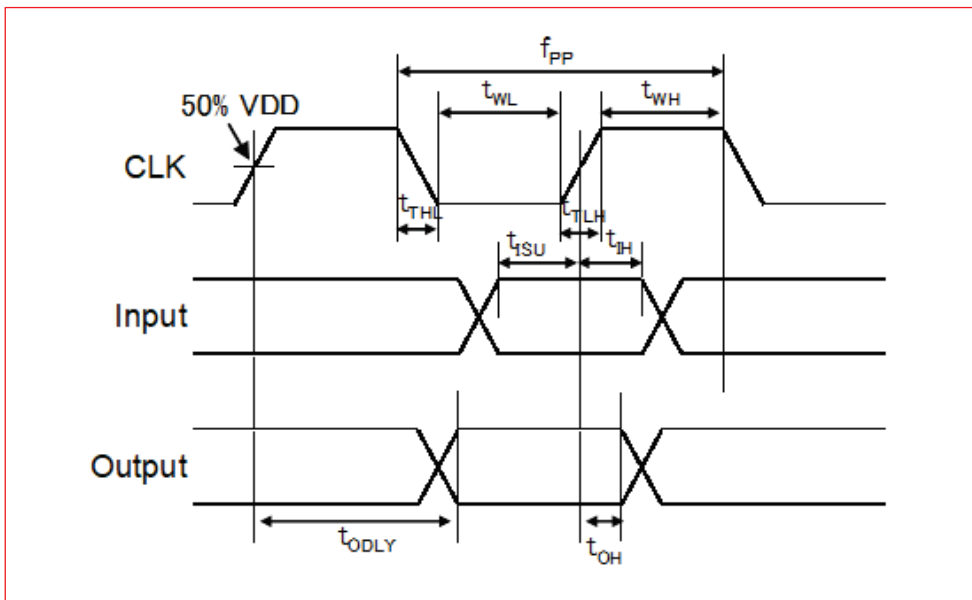


Timing is based on  $CL < 40$  pF load on CMD and Data.  
Minimum ( $V_{ih}$ ) =  $0.7 \cdot V_{DDIO}$  and maximum ( $V_{il}$ ) =  $0.2 \cdot V_{DDIO}$

### 13.1.2 High Speed Mode

The high-speed mode SDIO timing and parameters are shown in **Figure 14** and **Table 15**.

**Figure 14: SDIO Timing Diagram - High Speed Mode**



**Table 15: SDIO Timing Parameters - High Speed Mode**

Parameter	Symbol	Minimum	Typical	Maximum	Unit
<b>Clock CLK (All values are referred to minimum <math>V_{IH}</math> and maximum <math>V_{IL}</math>)</b>					
Frequency-Data Transfer Mode	$f_{PP}$	0		50	MHz
Frequency-Identification Mode	$f_{OD}$	0		400	kHz
Clock Low Time	$t_{WL}$	7			ns
Clock High Time	$t_{WH}$	7			ns
Clock Rise Time	$t_{TLH}$			3	ns
Clock Fall Time	$t_{THL}$			3	ns
<b>Inputs: CMD, DAT (referenced to CLK)</b>					
Input Setup Time	$t_{ISU}$	6			ns
Input Hold Time	$t_{IH}$	2			ns

Parameter	Symbol	Minimum	Typical	Maximum	Unit
<b>Outputs: CMD, DAT (referenced to CLK)</b>					
Output Delay Time-Data Transfer Mode	t <sub>ODLY</sub>			14	ns
Output Hold time	t <sub>OH</sub>	2.5			ns
Total System Capacitance (each line)	CL			40	pF

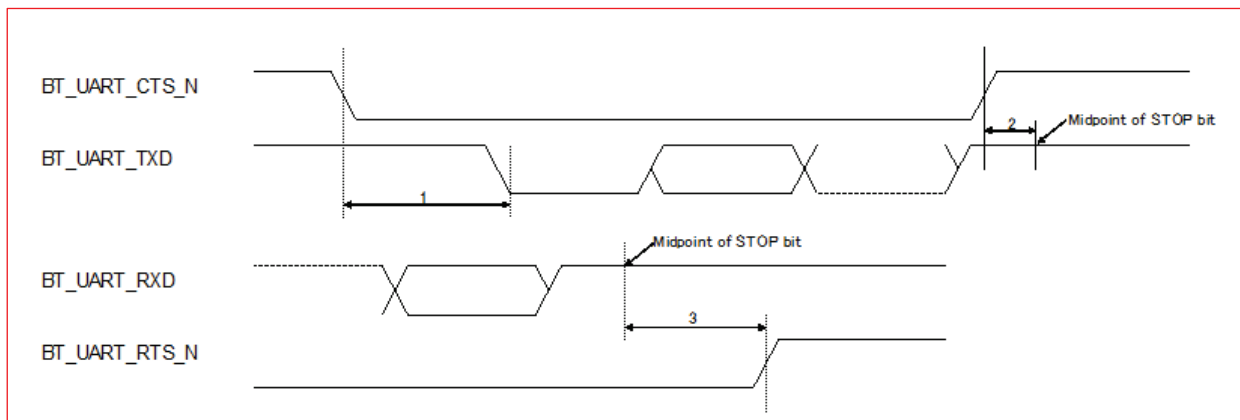


Timing is based on CL < 40 pF load on CMD and Data.  
Minimum (V<sub>ih</sub>) = 0.7\*VDDIO and maximum (V<sub>il</sub>) = 0.2\*VDDIO

## 13.2 Bluetooth UART Timing - Default Mode

Bluetooth UART timing diagram in default mode is shown in **Figure 15**.

**Figure 15: Bluetooth UART Timing Diagram - Default Mode**



**Table 16** shows the Bluetooth timing parameters in default mode.

**Table 16: Bluetooth UART Timing Parameters - Default Mode**

Reference	Description	Minimum	Typical	Maximum	Unit
1	Delay time, UART_CTS_N low to UART_TXD valid			1.5	Bit periods
2	Setup time, UART_CTS_N high before midpoint of stop bit.			0.5	Bit periods
3	Delay time, midpoint of stop bit to UART_RTS_N high			0.5	Bit periods

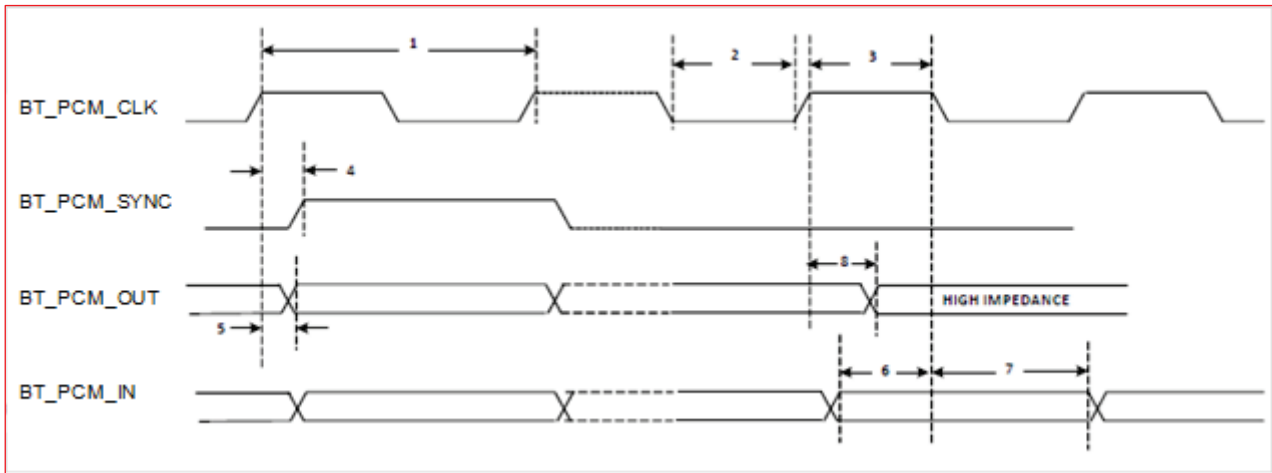
## 13.3 Bluetooth PCM Timing

This section describes the Bluetooth PCM timing sync signals along with their parameters for both long frame and short frame, as well as master and slave modes.

### 13.3.1 PCM Timing Short Frame Sync - Master Mode

**Figure 16** shows the PCM short frame sync signal in master mode.

**Figure 16: PCM Timing Short Frame Sync Signal - Master Mode**



**Table 17** lists information about PCM short frame sync in master mode.

**Table 17: Symbol Definitions for PCM Timing Short Frame Sync Signal - Master Mode**

Reference	Description	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency			12	MHz
2	PCM bit clock low	41			ns
3	PCM bit clock high	41			ns
4	PCM_SYNC delay	0		25	ns
5	PCM_OUT delay	0		25	ns
6	PCM_IN setup	8			ns
7	PCM_IN hold	8			ns
8	Delay from rising edge of PCM_CLK during last bit period to PCM_OUT becoming high impedance.	0		25	ns



### 13.3.2 PCM Timing Short Frame Sync - Slave Mode

Figure 17 shows the PCM short frame sync signal in slave mode.

Figure 17: PCM Timing Short Frame Sync Signal - Slave Mode

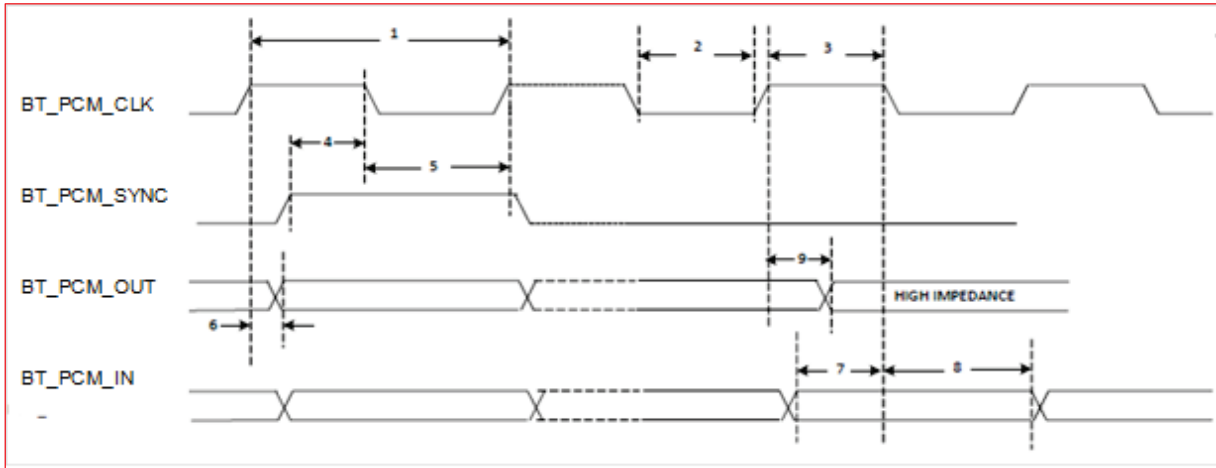


Table 18 lists information about PCM short frame sync in slave mode.

Table 18: Symbol Definitions for PCM Timing Short Frame Sync Signal - Slave Mode

Reference	Description	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency			12	MHz
2	PCM bit clock Low	41			ns
3	PCM bit clock High	41			ns
4	PCM_SYNC setup	8			ns
5	PCM_SYNC hold	8			ns
6	PCM_OUT delay	0		25	ns
7	PCM_IN setup	8			ns
8	PCM_IN hold	8			ns
9	Delay from rising edge of PCM_CLK during last bit period to PCM_OUT becoming high impedance	0		25	ns

### 13.3.3 PCM Timing Long Frame Sync - Master Mode

Figure 18 shows the PCM long frame sync signal in master mode.

Figure 18: PCM Timing Long Frame Sync Signal - Master Mode

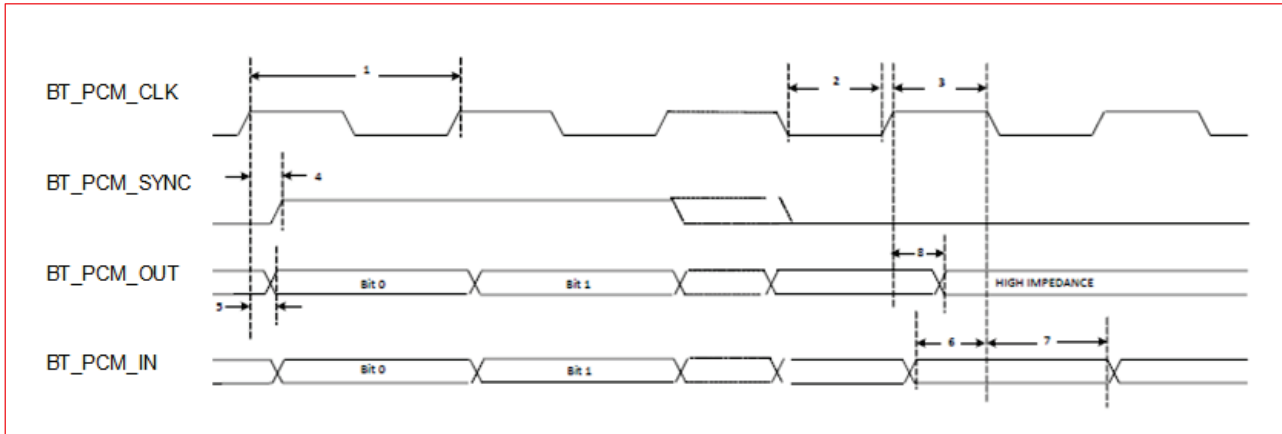


Table 19 lists information about PCM long frame sync in master mode.

Table 19: Symbol Definitions for PCM Timing Long Frame Sync Signal - Master Mode

Reference	Description	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency			12	MHz
2	PCM bit clock low	41			ns
3	PCM bit clock high	41			ns
4	PCM_SYNC delay	0		25	ns
5	PCM_OUT delay	0		25	ns
6	PCM_IN setup	8			ns
7	PCM_IN hold	8			ns
8	Delay from rising edge of PCM_CLK during last bit period to PCM_OUT becoming high impedance.	0		25	ns

### 13.3.4 PCM Timing Long Frame Sync - Slave Mode

Figure 19 shows PCM long frame sync signal in slave mode.

Figure 19: PCM Timing Long Frame Sync Signal - Slave Mode

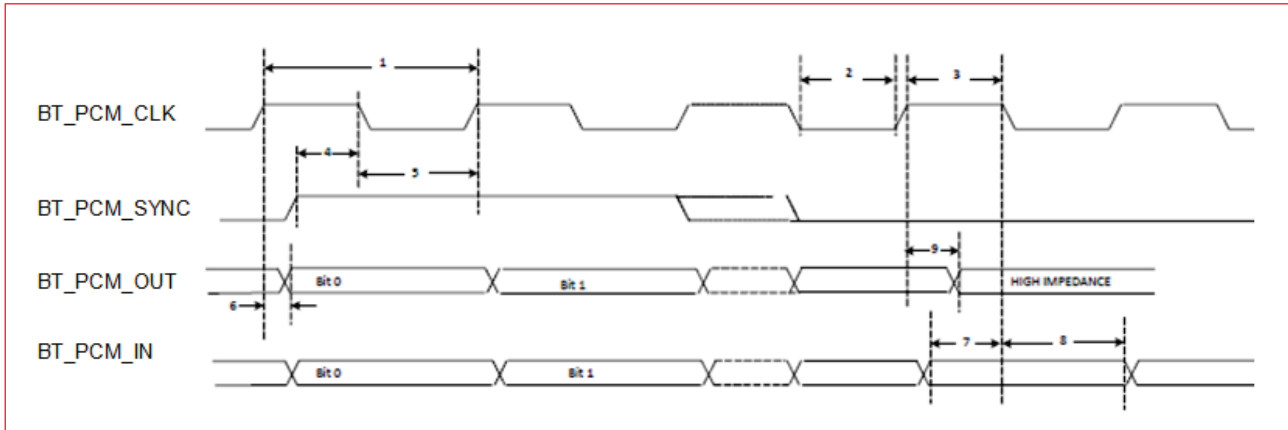


Table 20 lists information about PCM short frame sync in slave mode.

Table 20: Symbol Definitions for PCM Timing Long Frame Sync Signal - Slave Mode

Reference	Description	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency			12	MHz
2	PCM bit clock low	41			ns
3	PCM bit clock high	41			ns
4	PCM_SYNC setup	8			ns
5	PCM_SYNC hold	8			ns
6	PCM_OUT delay	0		25	ns
7	PCM_IN setup	8			ns
8	PCM_IN hold	8			ns
9	Delay from rising edge of PCM_CLK during last bit period to PCM_OUT becoming high impedance	0		25	ns

## 14 DC/RF Characteristics

This section defines the DC/RF characteristics for Type 1DX.

### 14.1 DC/RF Characteristics for IEEE 802.11b

**Table 21: Characteristics Values for IEEE 802.11b**

Items	Contents
Specification	IEEE 802.11b
Mode	DSSS / CCK
Frequency	2400 to 2483.5 MHz
Data Rate	1, 2, 5.5, 11 Mbps

**Conditions:** 25 °C, VBAT = 3.6V, VDDIO = 3.3V, Output power setting = 17 dBm, 11 Mbps mode

**Table 22: DC/RF Characteristics for IEEE 802.11b**

Items	Contents			
DC Characteristics	Minimum	Typical	Maximum	Unit
DC Current				
• Tx mode (1024 byte, 20 $\mu$ s interval)		320	370	mA
• Rx mode		47	60	mA
TX Characteristics	Minimum	Typical	Maximum	Unit
Output Power Tolerance)	15	17	19	dBm
Spectrum Mask				
• 1st side lobes		-43	-30	dBr
• 2nd side lobes		-54	-50	dBr
Power-on and Power-off Ramp			2.0	$\mu$ s
RF Carrier Suppression	15			dB
Modulation Accuracy (EVM)		15	35	%
Out band Spurious Emissions				
• 30 MHz to 1 GHz (BW = 100 kHz)			-36	dBm
• 1 GHz to 12.75 GHz (BW = 100 kHz)			-30	dBm
• 1.8 GHz to 1.9 GHz (BW = 100 kHz)			-47	dBm
• 5.15 GHz to 5.3 GHz (BW = 100 kHz)			-47	dBm
Rx Characteristics	Minimum	Typical	Maximum	Unit
Minimum Input Level (FER $\leq$ 8%)		-89	-76	dBm
Maximum Input Level (FER $\leq$ 8%)	-10			dBm
Adjacent Channel Rejection (FER $\leq$ 8%)	35			dB

## 14.2 DC/RF Characteristics for IEEE 802.11g

**Table 23: Characteristics Values for IEEE 802.11g**

Items	Contents
Specification	IEEE 802.11g
Mode	OFDM
Frequency	2400 to 2483.5 MHz
Data Rate	6, 9, 12, 18, 24, 36, 48, 54 Mbps

**Conditions:** 25 °C, VBAT = 3.6V, VDDIO = 3.3V, Output power setting = 13 dBm, 54 Mbps mode

**Table 24: DC/RF Characteristics for IEEE 802.11g**

Items	Contents			
DC Characteristics	Minimum	Typical	Maximum	Unit
DC Current				
• Tx mode (1024 byte, 20 $\mu$ s interval)		270	310	mA
• Rx mode		47	60	mA
TX Characteristics	Minimum	Typical	Maximum	Unit
Output Power (Tolerance)	11	13	15	dBm
Spectrum Mask				
• 9 MHz to 11 MHz (0 dB ~ -20 dB)		-33	-20	dBr
• 11 MHz to 20 MHz (-20 dB ~ -28 dB)		-41	-28	dBr
• 20 MHz to 30 MHz (-28 dB ~ -40 dB)		-53	-40	dBr
• 30 MHz to 33 MHz (-40 dB)		-53	-40	dBr
Constellation Error (EVM)		-30	-25	dB
Out band Spurious Emissions				
• 30 MHz to 1 GHz (BW = 100 kHz)			-36	dBm
• 1 GHz to 12.75 GHz (BW = 100 kHz)			-30	dBm
• 1.8 GHz to 1.9 GHz (BW = 100 kHz)			-47	dBm
• 5.15 GHz to 5.3 GHz (BW = 100 kHz)			-47	dBm
Rx Characteristics	Minimum	Typical	Maximum	Unit
Minimum Input Level (PER $\leq$ 10%)		-75	-65	dBm
Maximum Input Level (PER $\leq$ 10%)	-20			dBm
Adjacent Channel Rejection (PER $\leq$ 10%)	-1			dB

## 14.3 DC/RF Characteristics for IEEE 802.11n

**Table 25: Characteristics Values for IEEE 802.11n**

Items	Contents
Specification	IEEE 802.11n
Mode	OFDM
Frequency	2400 to 2483.5 MHz
Data Rate	6.5, 13, 19.5, 26, 39, 52, 58.5, 65 Mbps

**Conditions:** 25 °C, VBAT = 3.6V, VDDIO = 3.3V, Output power setting = 12 dBm, 65 Mbps mode

**Table 26: DC/RF Characteristics for IEEE 802.11n**

Items	Contents			
DC Characteristics	Minimum	Typical	Maximum	Unit
DC Current				
• Tx mode (1024 byte, 20 $\mu$ s interval)		260	300	mA
• Rx mode		47	60	mA
TX Characteristics	Minimum	Typical	Maximum	Unit
Output Power (Tolerance)	10	12	14	dBm
Spectrum Mask				
• 9 MHz to 11 MHz (0 dB ~ -20 dB)		-33	-20	dBr
• 11 MHz to 20 MHz (-20 dB ~ -28 dB)		-41	-28	dBr
• 20 MHz to 30 MHz (-28 dB ~ -45 dB)		-53	-45	dBr
• 30 MHz to 33 MHz (-45 dB)		-53	-45	dBr
Constellation Error (EVM)		-31	-27	dB
Out band Spurious Emissions				
• 30 MHz to 1 GHz			-36	dBm
• 1 GHz to 12.75 GHz			-30	dBm
• 1.8 GHz to 1.9 GHz			-47	dBm
• 5.15 GHz to 5.3 GHz			-47	dBm
Rx Characteristics	Minimum	Typical	Maximum	Unit
Minimum Input Level (PER $\leq$ 10%)		-73	-64	dBm
Maximum Input Level (PER $\leq$ 10%)	-20			dBm
Adjacent Channel Rejection (PER $\leq$ 10%)	-2			dB

## 14.4 DC/RF Characteristics for Bluetooth

Normal conditions: 25 °C, VBAT = 3.6V, VDDIO = 3.3V

Table 27: DC/RF Characteristics for Bluetooth

Items	Contents			
Bluetooth Specification (power class)	Version 2.1 + EDR (Class1)			
Channel Frequency (spacing)	2402 to 2480 MHz (1 MHz)			
<b>Current Consumption</b>	<b>Minimum</b>	<b>Typical</b>	<b>Maximum</b>	<b>Unit</b>
• Tx = Rx = DH5 (fully occupied)		28	60	mA
• Tx = Rx = 2DH5 (fully occupied)		25	50	mA
• Tx = Rx = 3DH5 (fully occupied)		25	50	mA
<b>Transmitter</b>	<b>Minimum</b>	<b>Typical</b>	<b>Maximum</b>	<b>Unit</b>
Output Power	6	10	14	dBm
Frequency Range	2400		2483.5	MHz
20 dB bandwidth			1	MHz
Adjacent Channel Power <sup>2</sup>				
• [M-N] = 2			-20	dBm
• [M-N] ≥ 3			-40	dBm
Modulation Characteristics				
• Modulation $\Delta f_{1\text{avg}}$	140		175	kHz
• Modulation $\Delta f_{2\text{max}}$	115			kHz
• Modulation $\Delta f_{2\text{avg}} / \Delta f_{1\text{avg}}$	0.8			
Carrier Frequency Drift				
• 1slot	-25		+25	kHz
• 3slot / 5slot	-40		+40	kHz
• Maximum drift rate			20	kHz/50 $\mu$ s
EDR Relative Power	-4		+1	dB
EDR Carrier Frequency Stability and Modulation Accuracy				
• $\omega_i$	-75		+75	kHz
• $\omega_i + \omega_o$	-75		+75	kHz
• $\omega_o$	-10		+10	kHz
• RMS DEVM (DQPSK)			20	%
• Peak DEVM (DQPSK)			35	%
• 99% DEVM (DQPSK)			30	%
• RMS DEVM (8DPSK)			13	%
• Peak DEVM (8DPSK)			25	%
• 99% DEVM (8DPSK)			20	%
Out-of-Band Spurious Emissions				
• 30-1000 MHz			-36	dBm
• 1000-12750 MHz			-30	dBm
• 1800-1900 MHz			-47	dBm
• 5150-5300 MHz			-47	dBm
<b>Receiver</b>	<b>Minimum</b>	<b>Typical</b>	<b>Maximum</b>	<b>Unit</b>
Sensitivity (BER ≤ 0.1%)		-91	-80	dBm
C/I Performance (BER ≤ 0.1%) <sup>3</sup>				
• Co-channel			11	dB

<sup>2</sup> Up to three spurious responses within Bluetooth limits are allowed.

<sup>3</sup> Up to five spurious responses within Bluetooth limits are allowed.

Items	Contents			
• 1 MHz			0	dB
• 2 MHz			-30	dB
• 3 MHz			-40	dB
• image (+4 MHz)			-9	dB
• image +/- 1 MHz			-20	dB
Maximum Input Level (PER ≤ 0.1%)	-20			dBm
EDR Sensitivity (PER ≤ 0.007%)				
• 8DPSK		-88	-77	dBm

## 14.5 DC/RF Characteristics for Bluetooth Low Energy

**Conditions:** Conditions: 25 °C, VBAT = 3.6V, VDDIO = 3.3V

**Table 28: DC/RF Characteristics for BLE**

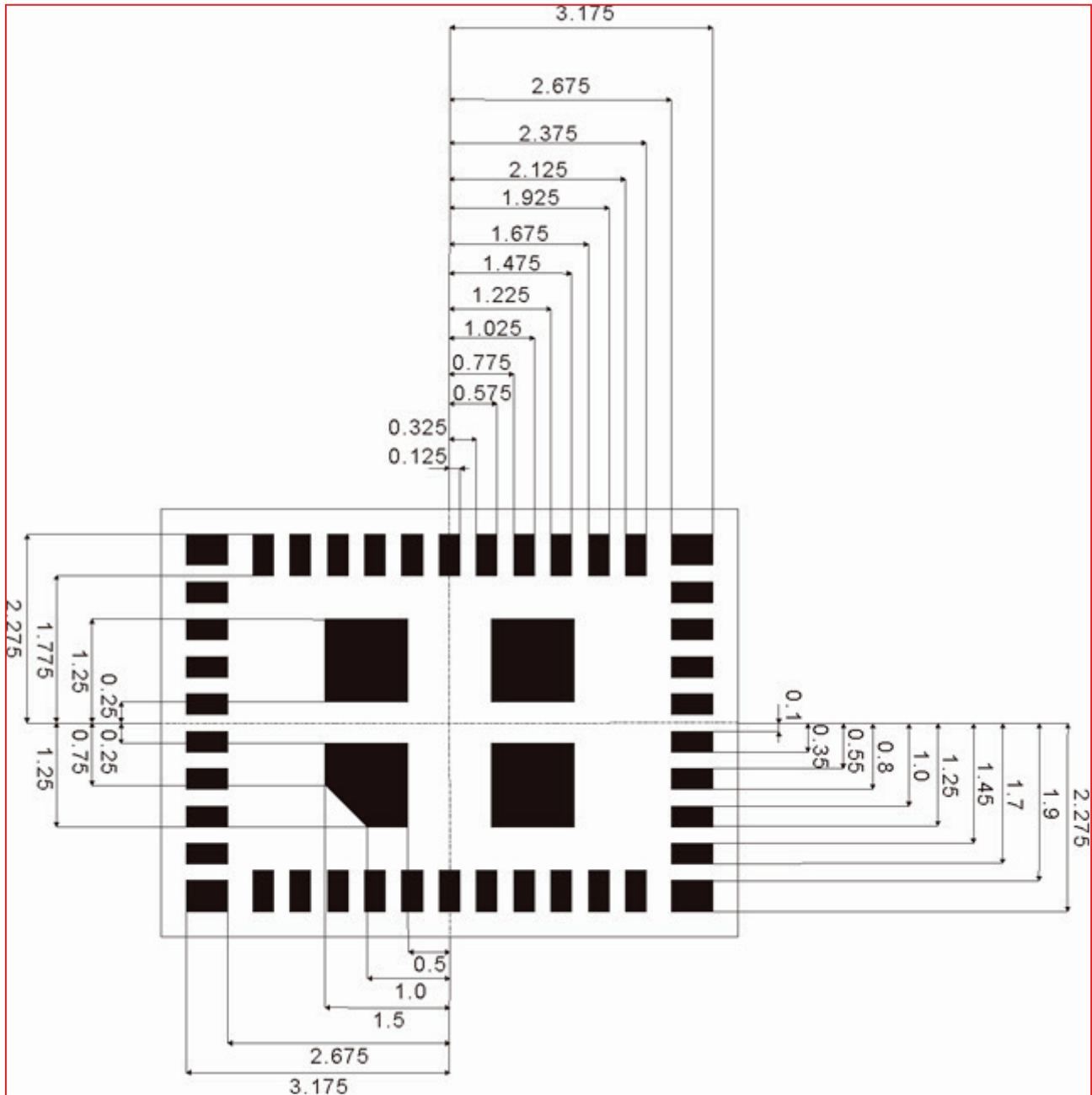
Items	Contents			
Bluetooth Specification (power class)	Version 5.1 (LE)			
Channel Frequency (spacing)	2402 to 2480 MHz (2 MHz)			
Number of RF Channel	40			
Item / Condition	Minimum	Typical	Maximum	Unit
Center Frequency	2402		2480	MHz
Channel Spacing		2		MHz
Number of RF Channel		40		
Output Power			10	dBm
Modulation Characteristics				
• $\Delta f_{1\text{avg}}$	225		275	kHz
• $\Delta f_{2\text{max}}$ (at 99.9%)	185			kHz
• $\Delta f_{2\text{avg}} / \Delta f_{1\text{avg}}$	0.8			
Carrier Frequency Offset and Drift				
1) Frequency offset			150	kHz
2) Frequency drift			50	kHz
3) Drift rate			20	kHz
Receiver Sensitivity (PER < 30.8%)		-95	-70	dBm
Maximum Input Signal Level (PER < 30.8%)	-10			dBm
PER Report Integrity (-30 dBm input)	50		65.4	%



## 15 Land Pattern

The land pattern is shown in **Figure 20**.

**Figure 20: Land Pattern (Unit: mm)**



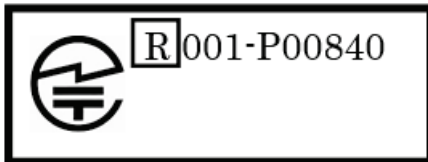
## 16 Radio Regulatory Certification by Country for LBEE5KL1DX

This section includes user manual for all the following countries:

- Japan
- FCC
- ISED
- Europe

### 16.1 Japan

Regarding Japan Radio Certification of 1DX



This module is the product that has been authorized “Japan Radio Certification” (Certification of Construction Type) based on type approval system.

Also, it is recommended to describe the following contents in the end product that is built in this module or the user manual.



This product has built-in specified radio equipment which authorized “Japan Radio Certification” (certification number: 001-P00840) based on type approval system.

#### 16.1.1 Power Levels for Japan

**Table 29** shows the per antenna port WLAN power table for Japan.

**Table 29: Japan Power Level 2.4GHz WLAN Per Antenna Port**

Mode	Data Rate	Maximum Tune Up Tolerance [dBm]
		Ch. 1-13
IEEE 802 11b	All Rates	17
IEEE 802 11g	All Rates	13
IEEE 802 11n (HT20)	All Rates	12

**Table 30** shows the per antenna port Bluetooth power table for Japan.

**Table 30: Japan Power Level 2.4 GHz BT/BLE Per Antenna Port**

Mode	Maximum Tune Up Tolerance (dBm)
BR	8.0
LE	8.0
LE 2 Mbps	8.0



The Bluetooth power **Table 30** is valid for all regions (Japan, USA, Canada, and Europe).

## 16.1.2 Antenna List

Only recommend PCB trace antenna. If end customer wants to use other type of antenna, customer need to take care of certification. Recommended antenna for 1DX is shown below.

Antenna type	Monopole (pattern antenna)
Antenna gain	0.6 dBi (peak)

## 16.2 FCC

### FCC ID: 772C-LB1DX

This is for OEM integration only. This device cannot be sold to general public. Therefore, OEM must include the following statements on the product and in the installation manual notice as per the FCC/IC requirement.

### 16.2.1 Information to Display on Host Device and User Manual

#### 16.2.1.1 Information on Host Device

Please describe the following warning on the final product which contains this module.

- Contains Transmitter Module FCC ID: VPYLB1DX or Contains FCC ID: VPYLB1DX

#### 16.2.1.2 Information in User Manual

Please describe the following warning to the manual.

- **FCC CAUTION:** Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.
- This transmitter must not be co-located or operated in conjunction with any other antenna or transmitter.



This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions:

- This device may not cause harmful interference.
- This device must accept any interference received, including interference that may cause undesired operation.



When a product is small to include all the text mentioned above, the text above can be mentioned in its manual.

## 16.2.2 Equipment Installation for FCC

There are two types of installation for host device.

### 16.2.2.1 Mobile Equipment

Equipment used at position in which the spaces between human body and antenna exceeded 20cm. When installing it in a mobile equipment. Please describe the following warning to the manual.



- This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment and meets the FCC radio frequency (RF) Exposure Guidelines. This equipment should be installed and operated keeping the radiator at least 20cm or more away from person's body.
- RF Exposure requirements are met when installed in mobile equipment.

### 16.2.2.2 Portable Equipment

Equipment for which the spaces between human body and antenna are used within 20cm. When installing it in a portable equipment. Please describe the following warning to the manual.



- This module cannot be installed in portable equipment without further testing and a change to FCC's grant of authorization.
- Contact Murata regarding portable applications.

## 16.2.3 OEM Integration

This device is intended only for OEM integrators under the following conditions:

- The antenna must be installed such that 20 cm is maintained between the antenna and users, and
- The transmitter module may not be co-located with any other transmitter or antenna.
- The use of an antenna with gain less than 1.4 dBi.

Further transmitter test will not be required as long as the above 3 conditions are met. However, the OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this module installed.



In the event that these conditions cannot be met (for example certain laptop configurations or co-location with another transmitter), then the FCC authorization is no longer considered valid, and the FCC ID cannot be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate FCC authorization.

## 16.2.4 End Product Labeling

This transmitter module is authorized only for use in device where the antenna may be installed such that 20 cm may be maintained between the antenna and users. The final end product must be labeled in a visible area with the following: "Contains FCC ID: XXXXXXXXXX". The grantee's FCC ID can be used only when all FCC compliance requirements are met.

## 16.2.5 Manual Information to the End User

The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module in the user's manual of the end product which integrates this module.



The end user manual shall include all required regulatory information/warning as show in this manual.

## 16.2.6 Power Levels for FCC and ISCED

**Table 31** shows the per antenna port WLAN power table for USA and Canada.

**Table 31: FCC/ISED Power Level Per Antenna Port**

Mode	Data Rate	Maximum Tune Up Tolerance [dBm]
		Ch. 1-11
IEEE 802 11b	All Rates	17
IEEE 802 11g	All Rates	13
IEEE 802 11n (HT20)	All Rates	12

## 16.3 ISCED

**IC:** 772C-LB1DX

This is for OEM integration only. This device cannot be sold to general public. Therefore, OEM must include the following statements on the product and in the installation manual notice as per the FCC/IC requirement.

### 16.3.1 Information to Display on Host Device

Please describe the following warning on the final product while installing in it:

- Contains IC:772C-LB1DX

#### English Version

This device complies with Industry Canada's applicable license-exempt RSSs. Operation is subject to the following two conditions:

- This device may not cause interference; and
- This device must accept any interference, including interference that may cause undesired operation of the device.

#### French Version

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes:

- l'appareil ne doit pas produire de brouillage.
- l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.



When a product is small to include all the text mentioned above, the text above can be mentioned in its manual.

## 16.3.2 Equipment Installation for ISED

There are two types of installation for host device.

### 16.3.2.1 Mobile Equipment

Equipment used at position in which the spaces between human body and antenna exceeded 20 cm. When installing it in a mobile equipment. Please describe the following warning to the manual.

#### English Version

This equipment complies with IC radiation exposure limits set forth for an uncontrolled environment and meets RSS-102 of the IC radio frequency (RF) Exposure rules. This equipment should be installed and operated keeping the radiator at least 20cm or more away from person's body.

#### French Version

Cet équipement est conforme aux limites d'exposition aux rayonnements énoncées pour un environnement non contrôlé et respecte les règles d'exposition aux fréquences radioélectriques (RF) CNR-102 de l'IC. Cet équipement doit être installé et utilisé en gardant une distance de 20 cm ou plus entre le radiateur et le corps humain.



RF exposure requirements are met when installed in mobile equipment.

### 16.3.2.2 Portable Equipment

Equipment for which the spaces between human body and antenna are used within 20 cm. When installing it in a portable equipment. Please describe the following warning to the manual.



- This module cannot be installed in portable equipment without further testing and a change to FCC's grant of authorization.
- Contact Murata regarding portable applications.

## 16.3.3 OEM Integration

#### English Version

This device is intended only for OEM integrators under the following conditions:

1. The antenna must be installed such that 20 cm is maintained between the antenna and users, and
2. The transmitter module may not be co-located with any other transmitter or antenna.
3. The use of an antenna with gain less than 1.4 dBi.

As long as the 3 conditions above are met, further transmitter test will not be required. However, the OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this module installed.

#### French Version

Cet appareil est conçu uniquement pour les intégrateurs OEM dans les conditions suivantes: (Pour utilisation de dispositif module)

1. L'antenne doit être installée de telle sorte qu'une distance de 20 cm est respectée entre l'antenne et les utilisateurs, et
2. Le module émetteur peut ne pas être coimplanté avec un autre émetteur ou antenne.
3. L'utilisation d'une antenne avec un gain inférieur à 1,4 dBi.

**English Version**

Further transmitter test will not be required as long as the above 3 conditions are met. However, the OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this module installed.

**French Version**

Tant que les 3 conditions ci-dessus sont remplies, des essais supplémentaires sur l'émetteur ne seront pas nécessaires. Toutefois, l'intégrateur OEM est toujours responsable des essais sur son produit final pour toutes exigences de conformité supplémentaires requis pour ce module installé.

**English Version****Important Note:**

In the event that these conditions cannot be met (for example certain laptop configurations or co-location with another transmitter), then the FCC authorization is no longer considered valid, and the FCC ID cannot be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate FCC authorization.

**French Version****Note Importante:**

Dans le cas où ces conditions ne peuvent être satisfaites (par exemple pour certaines configurations d'ordinateur portable ou de certaines co-localisation avec un autre émetteur), l'autorisation du Canada n'est plus considéré comme valide et l'ID IC ne peut pas être utilisé sur le produit final. Dans ces circonstances, l'intégrateur OEM sera chargé de réévaluer le produit final (y compris l'émetteur) et l'obtention d'une autorisation distincte au Canada.

## 16.3.4 End Product Labeling

**English Version****End Product Labeling**

This transmitter module is authorized only for use in device where the antenna may be installed such that 20 cm may be maintained between the antenna and users. The final end product must be labeled in a visible area with the following: "Contains FCC ID:XXXXXXXXXX". The grantee's FCC ID can be used only when all FCC compliance requirements are met.

**French Version****Plaque signalétique du produit final**

Ce module émetteur est autorisé uniquement pour une utilisation dans un dispositif où l'antenne peut être installée de telle sorte qu'une distance de 20cm peut être maintenue entre l'antenne et les utilisateurs. Le produit final doit être étiqueté dans un endroit visible avec l'inscription suivante: "Contient des IC:".

## 16.3.5 Manual Information to the End User

**English Version****Manual Information To the End User**

The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module in the user's manual of the end product which integrates this module.

The end user manual shall include all required regulatory information/warning as show in this manual.

**French Version****Manuel d'information à l'utilisateur final**

L'intégrateur OEM doit être conscient de ne pas fournir des informations à l'utilisateur final quant à la façon d'installer ou de supprimer ce module RF dans le manuel de l'utilisateur du produit final qui intègre ce module.

Le manuel de l'utilisateur final doit inclure toutes les informations réglementaires requises et avertissements comme indiqué dans ce manuel.

## 16.4 Europe

**Table 32** shows the per antenna port WLAN power table for Europe.

**Table 32: Europe Power Level Per Antenna Port**

Mode	Data Rate	Maximum Tune Up Tolerance [dBm]
		Ch. 1-13
IEEE 802 11b	All Rates	17
IEEE 802 11g	All Rates	13
IEEE 802 11n (HT20)	All Rates	12



## 17 Tape and Reel Packing

This section provides the general specifications for tape and reel packing.

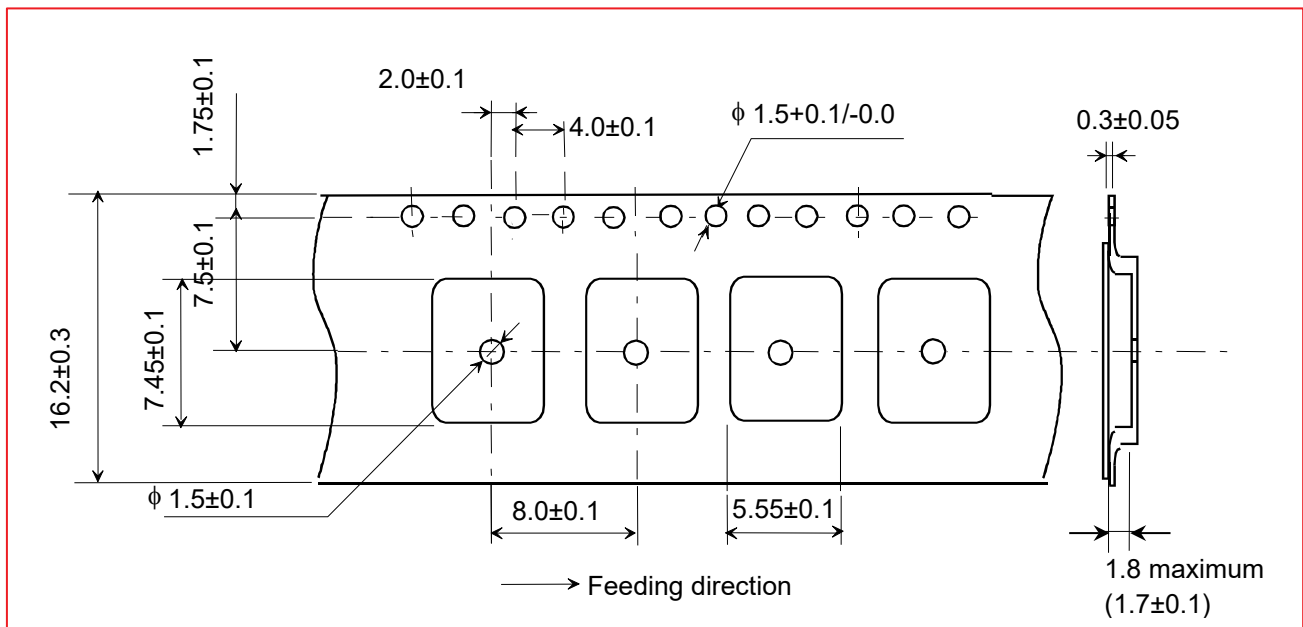
### 17.1 Dimensions of Tape (Plastic Tape)

The dimension of the tape is as follows:

- The corner and ridge radiuses (R) of inside cavity are 0.3 mm maximum.
- Cumulative tolerance of 10 pitches of the sprocket hole is +/-0.2 mm.
- Measuring of cavity positioning is based on cavity center in accordance with JIS/IES standard.

**Figure 21** is a graphical representation of the tape dimension (plastic tape).

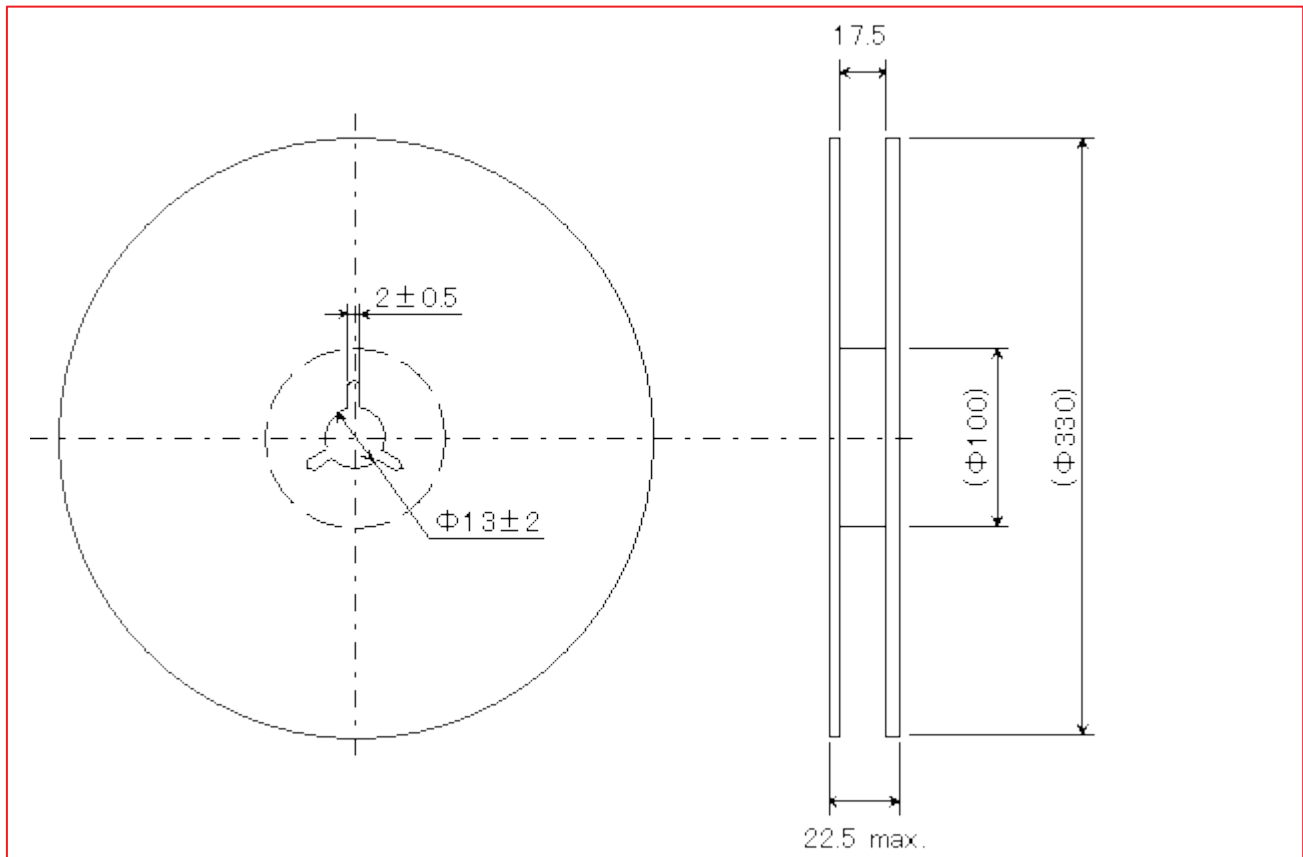
**Figure 21: Dimensions of Tape (Plastic Tape)**



## 17.2 Dimension of Reel

Figure 22 shows the reel dimensions.

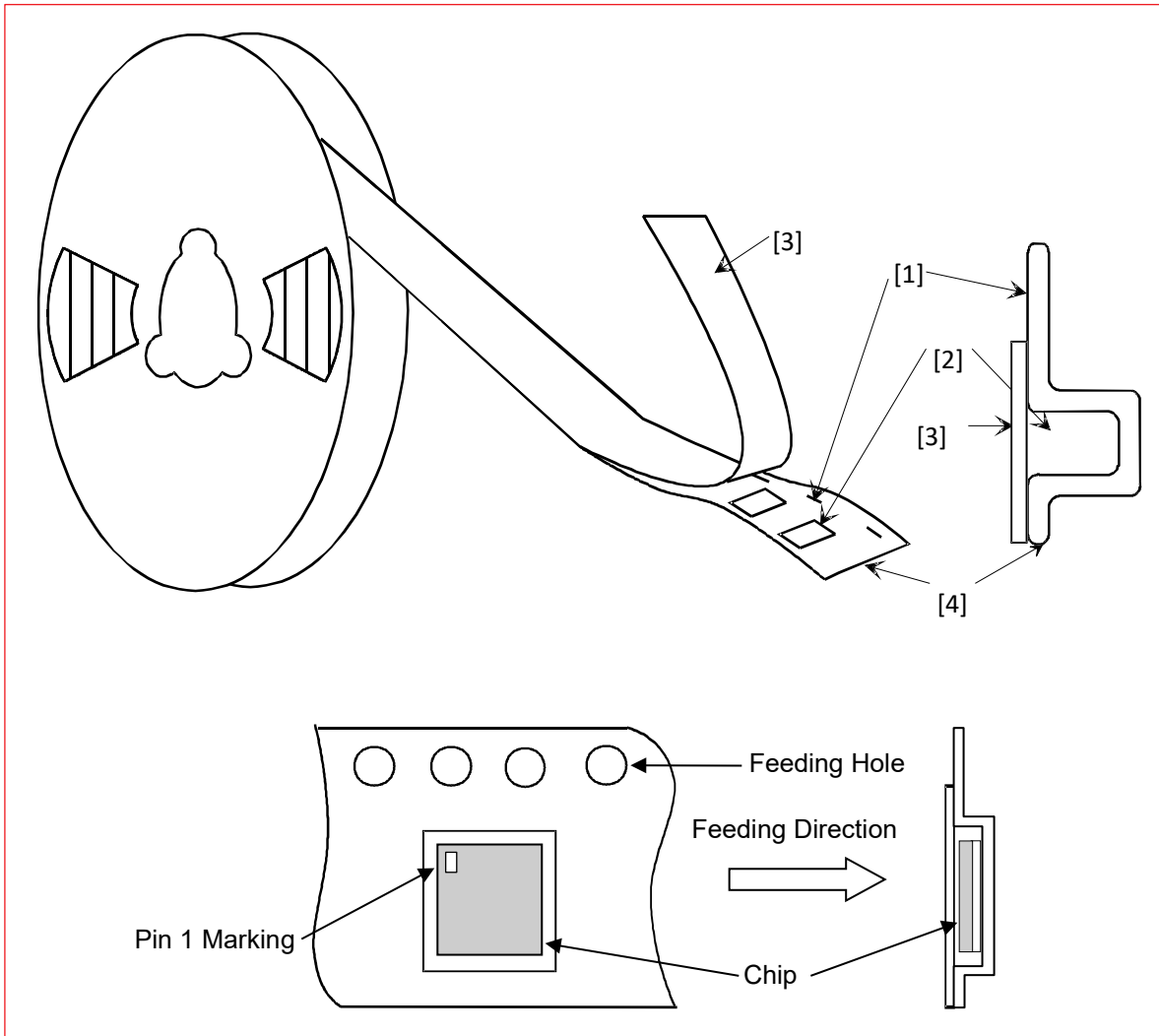
Figure 22: Dimensions of Reel (Unit: mm)



## 17.3 Taping Diagrams




Figure 23 shows the tapings diagrams.

Figure 23: Taping Diagrams



The taping specifications are described in **Table 33**.

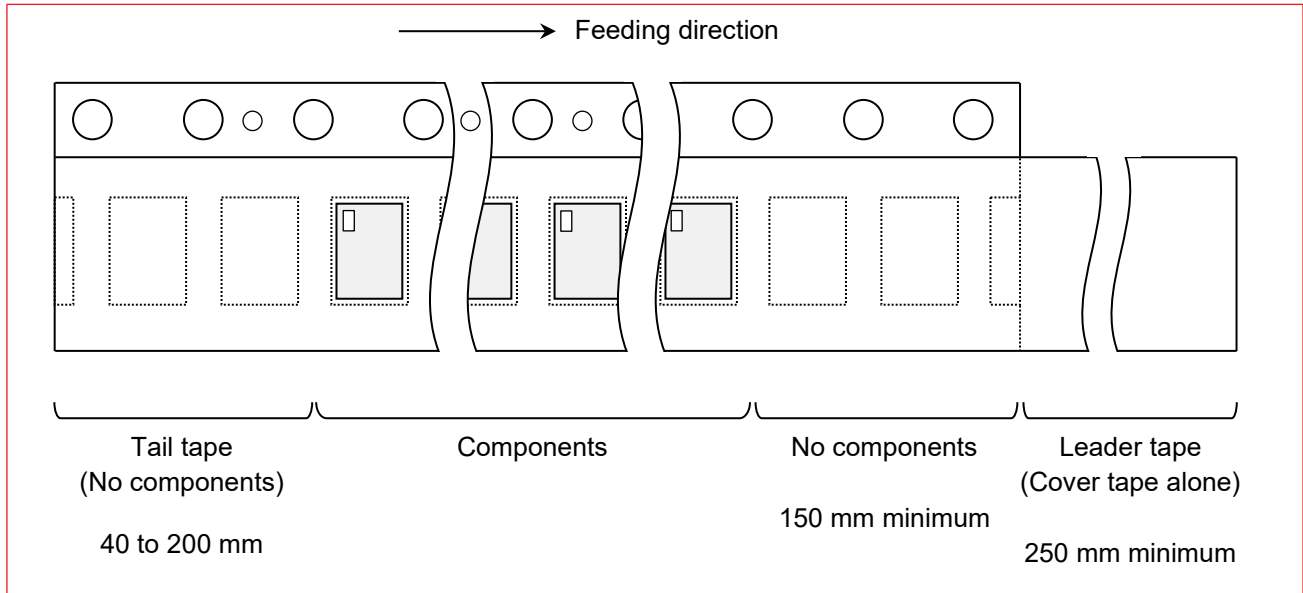
**Table 33: Taping Specifications**

Mark	Description
1	Feeding Hole. As specified in <a href="#">Dimensions of Tape (Plastic tape)</a> 
2	Hole for chip. As specified in <a href="#">Dimensions of Tape (Plastic tape)</a> 
3	Cover tape. 62 μm in thickness
4	Base tape. As specified in <a href="#">Dimensions of Tape (Plastic tape)</a> 

## 17.4 Leader and Tail Tape

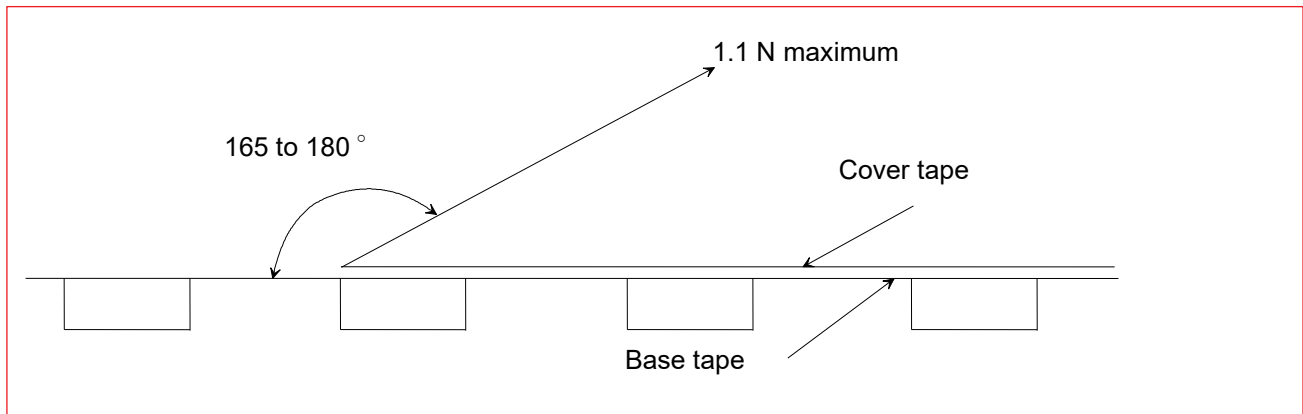
Cover tape, cavity tape and reel are made the anti-static processing. The leader and tail tape are shown in **Figure 24**.

**Figure 24: Leader and Tail Tape**



1. The tape for chips is wound clockwise, the feeding holes to the right side as the tape is pulled toward the user.
2. The cover tape and base tape are not adhered at no components area for 250 mm minimum.
3. Tear off strength against pulling of cover tape: 5 N minimum.
4. Packaging unit: 1000 pcs. / Reel
5. Tape material:
  - Base tape: Plastic
  - Reel: Plastic
  - Cover tape, cavity tape and reel are made the anti-static processing.
6. Peeling off force: 1.1 N maximum in the direction of peeling as shown in **Figure 25**.

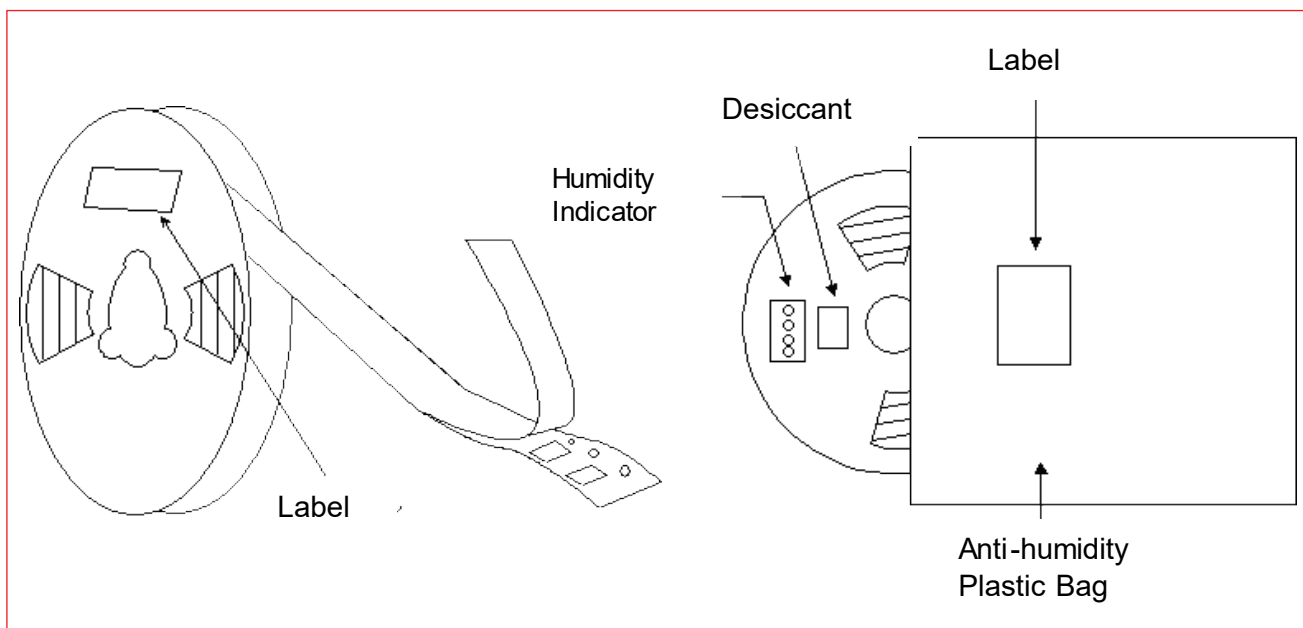
**Figure 25: Peeling Off Force**



## 17.5 Packaging (Humidity Proof Packing)

**Figure 26** shows the humidity proof packaging.

**Figure 26: Humidity Proof Packaging**



Tape and reel must be sealed with the anti-humidity plastic bag. The bag contains the desiccant and the humidity indicator.

## 18 Notice

### 18.1 Storage Conditions

- Please use this product within 6 months after receipt.
- The product shall be stored without opening the packing under the ambient temperature from 5 to 35 °C and humidity from 20 ~ 70 %RH (packing materials, in particular, may be deformed at the temperature over 40 °C)
- The product left more than 6 months after reception; the solderability needs to be confirmed before it is used.
- The product shall be stored in noncorrosive gas (Cl<sub>2</sub>, NH<sub>3</sub>, SO<sub>2</sub>, NO<sub>x</sub>, etc.).
- Any excess mechanical shock including, but not limited to, sticking the packing materials by sharp object, and dropping the product, shall not be applied as that will damage the packing materials.
- This product is applicable to MSL3 (Based on JEDEC Standard J-STD-020)
  - After the packing is opened, the product shall be stored at ≤ 30 °C / ≤ 60 %RH and the product *should be* used within 168 hours after opening.
  - When the color of the indicator in the packing is changed, the product *should be* baked before soldering.
- Baking condition: 125 +5/-0 °C, 24 hours, 1 time
- The products shall be baked on the heat-resistant tray because the material (Base Tape, Reel Tape and Cover Tape) is not heat-resistant.

### 18.2 Handling Conditions

Be careful while handling or transporting products because excessive stress or mechanical shock may break the products.

Handle with care if you suspect that products may have cracks or damages on their terminals. If there is any such damage, the characteristics of products may change. *Do not touch* products with bare hands as that may cause poor solderability and destroy static electrical charge.

### 18.3 Standard PCB Design (Land Pattern and Dimensions)

All the ground terminals should be connected to the ground patterns. Furthermore, the ground pattern should be provided between IN and OUT terminals. Please refer to the specifications for the standard land dimensions.

The recommended land pattern and dimensions should be as per Murata's standard. The characteristics of products may vary depending on the pattern drawing method, grounding method, land dimensions, land forming method of the NC terminals and the PCB material and thickness. Therefore, be sure to verify the characteristics in the actual set. When using non-standard lands, contact Murata in advance.

### 18.4 Notice for Chip Placer

When placing products on the PCB, products may be stressed and broken by uneven forces from a worn-out chucking locating claw or a suction nozzle. To prevent products from damages, be sure to

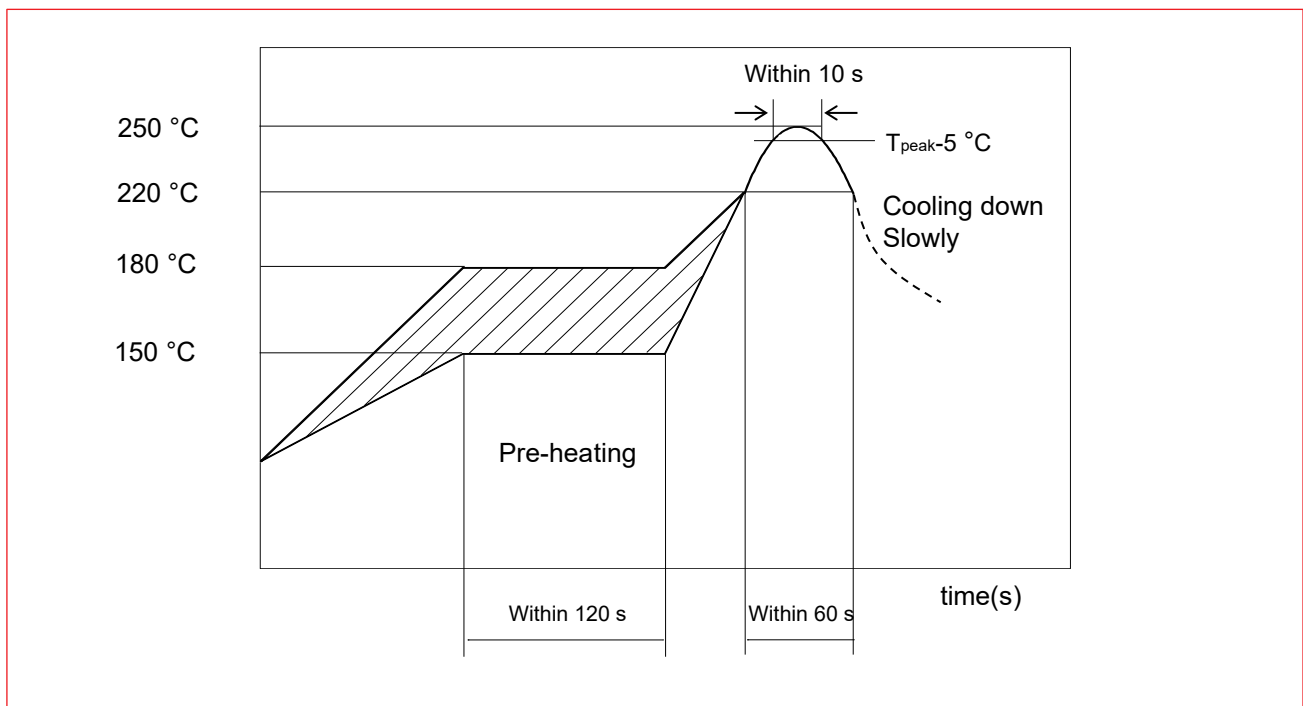
follow the specifications for the maintenance of the chip placer being used. For the positioning of products on the PCB, be aware that mechanical chucking may damage products.

## 18.5 Soldering Conditions

The recommendation conditions of soldering are as in **Figure 27**.

Soldering must be carried out by the above-mentioned conditions to prevent products from damaging. Set up the highest temperature of reflow within 260 °C. Contact Murata before use concerning other soldering conditions.

**Figure 27: Reflow Soldering Standard Conditions (Example)**



Please use the reflow within 2 times.

Use rosin type flux or weakly active flux with a chlorine content of 0.2 wt. % or less.

## 18.6 Cleaning

Since this product is moisture sensitive, cleaning is not recommended. If any cleaning process is done the customer is responsible for any issues or failures caused by the cleaning process.

## 18.7 Operational Environment Conditions

Products are designed to work for electronic products under normal environmental conditions (ambient temperature, humidity, and pressure). Therefore, products have no problems to be used under the similar conditions to the above-mentioned. However, if products are used under the following circumstances, it may damage products and leakage of electricity and abnormal temperature may occur.

- In atmosphere containing corrosive gas (Cl<sub>2</sub>, NH<sub>3</sub>, SO<sub>x</sub>, NO<sub>x</sub> etc.).
- In atmosphere containing combustible and volatile gases.
- Dusty place.
- Direct sunlight place.
- Water splashing place.
- Humid place where water condenses.
- Freezing place.



If there is any chance of using the products under the conditions listed above, consult with Murata before actual use.



Do not apply static electricity or excessive voltage while assembling and measuring the products, as it might be a cause of degradation or destruction to apply static electricity to products.

## 18.8 Input Power Capacity

Products shall be used in the input power capacity as specified in this specification.

Inform Murata beforehand, in case that the components are used beyond such input power capacity range.



## 19 Preconditions to Use Our Products



PLEASE READ THIS NOTICE BEFORE USING OUR PRODUCTS.

Please make sure that your product has been evaluated and confirmed from the aspect of the fitness for the specifications of our product when our product is mounted to your product.

All the items and parameters in this product specification/datasheet/catalog have been prescribed on the premise that our product is used for the purpose, under the condition and in the environment specified in this specification. You are requested not to use our product deviating from the condition and the environment specified in this specification.

Please note that the only warranty that we provide regarding the products is its conformance to the specifications provided herein. Accordingly, we shall not be responsible for any defects in products or equipment incorporating such products, which are caused under the conditions other than those specified in this specification.

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- Aircraft equipment.
- Aerospace equipment.
- Undersea equipment.
- Power plant control equipment.
- Medical equipment.
- Traffic signal equipment.

- Burning / explosion control equipment.
- Disaster prevention / crime prevention equipment.
- Transportation equipment (vehicles, trains, ships, elevator, etc.).
- Application of similar complexity and/ or reliability requirements to the applications listed in the above.

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Moreover, you must comply with "foreign exchange and foreign trade law", the "U.S. export administration regulations", etc.

Please note that we may discontinue the manufacture of our products, due to reasons such as end of supply of materials and/or components from our suppliers.

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## Revision History

Revision Code	Date	Changed Item	Comment
	2014.12.01	First Issue	
A	2014.12.04	6. Dimensions, Markings and Terminal Configurations 7.2 Pin Descriptions	<ul style="list-style-type: none"> <li>Corrected m1 and m2 of Dimensions</li> <li>Corrected VDDIO of Rating</li> </ul>
B	2015.01.23	6. Dimensions, Markings and Terminal Configurations	<ul style="list-style-type: none"> <li>Correction</li> </ul>
C	2015.02.09	4. Block Diagram	<ul style="list-style-type: none"> <li>Correction</li> </ul>
D	2015.03.04	7.2 Pin Descriptions 14. DC/RF Characteristics	<ul style="list-style-type: none"> <li>Corrected VBAT voltage</li> <li>Correction</li> </ul>
E	2015.03.26	6. Dimensions, Markings and Terminal Configurations 14. DC/RF Characteristics  16. Reference circuit 18. Tape and Reel Packing	<ul style="list-style-type: none"> <li>Correction: Spec fixed</li> <li>Fixed values on items described TBD</li> <li>Updated conditions VBAT voltage</li> <li>Correction: Spec fixed</li> </ul>
F	2015.06.19	7.3. SDIO Pin Descriptions 14.5. DC/RF Characteristics for Bluetooth Low Energy	<ul style="list-style-type: none"> <li>Added note of SDIO</li> <li>Added BLE spec</li> </ul>
G	2015.07.21	7.1. Operating condition  13. Reference Circuit	<ul style="list-style-type: none"> <li>Corrected Conditions VBAT voltage, Specification Temperature Range</li> <li>Add recommend parts name</li> </ul>
H	2015.08.26	14. DC/RF Characteristics	<ul style="list-style-type: none"> <li>Addition of typical values</li> </ul>
I	2015.09.26	4. Dimensions, Marking and Terminal Configurations 11. Land pattern	<ul style="list-style-type: none"> <li>Addition</li> <li>Addition</li> </ul>
J	2016.02.08	14.5. DC/RF Characteristics for Bluetooth Low Energy	<ul style="list-style-type: none"> <li>Added BLE Rx spec</li> </ul>
K	2016.02.29	4. Dimensions, Marking and Terminal Configurations 7.1. Module Pin Layout 6.2 Power Up Sequence	<ul style="list-style-type: none"> <li>Added marking information</li> <li>Corrected terminal conditions</li> <li>Correction</li> </ul>
L	2016.03.18	6. Dimensions, Marking and Terminal Configurations 7.1. Module Pin Layout	<ul style="list-style-type: none"> <li>Added structure</li> <li>Corrected terminal conditions</li> </ul>
M	2016.11.24	5. Certification Information 7.1 Module Pin Layout	<ul style="list-style-type: none"> <li>Addition</li> <li>Added pin layout</li> </ul>
N	2016.12.14	Appendix	<ul style="list-style-type: none"> <li>Addition</li> </ul>
O	2017.02.28	IC Part Number	<ul style="list-style-type: none"> <li>Changed</li> </ul>
P	2018.03.20	13. Reference Circuit	<ul style="list-style-type: none"> <li>Added 32.768 kHz X'tal in the reference circuit.</li> </ul>
Q	2018.05.08	1. Scope 4.2. Bluetooth® Qualification	<ul style="list-style-type: none"> <li>Updated Bluetooth version with 4.2</li> <li>Updated QDID</li> </ul>
R	2018.06.14	5.1. Dimensions	<ul style="list-style-type: none"> <li>Correction</li> </ul>
S	2018.07.11	4.1.4. Certification Information	<ul style="list-style-type: none"> <li>Updated (Europe)</li> </ul>
T	2019.05.16	16. Preconditions to Use Our Products Appendix	<ul style="list-style-type: none"> <li>Updated</li> <li>Added user manual for Japan</li> </ul>
U	2019.12.06	1. Scope 4.2. Bluetooth Qualification	<ul style="list-style-type: none"> <li>Updated Bluetooth version with 5.1</li> <li>Updated QDID</li> </ul>
V	2022.06.06	Title 1. Scope	<ul style="list-style-type: none"> <li>Silicon Manufacturer's name is revised</li> </ul>
W	2022.12.10	2. Key Features	<ul style="list-style-type: none"> <li>Updated information</li> </ul>

Revision Code	Date	Changed Item	Comment
		3. Part Number  13. Reference Circuit Appendix	<ul style="list-style-type: none"><li>• Added Embedded Artists' M.2 module information. Renamed section.</li><li>• Moved section to HW app note.</li><li>• Moved Appendix information into Sections 16.</li><li>• Moved antenna sections to HW app note.</li></ul> Updated to new format



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